09936073 24/09/2003

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NEWS	1		Web Page URLs for STN Seminar Schedule - N. America
NEWS	2		"Ask CAS" for self-help around the clock
NEWS	3	SEP 09	CA/CAplus records now contain indexing from 1907 to the present
NEWS	4	Jul 15	Data from 1960-1976 added to RDISCLOSURE
NEWS	5	Jul 21	Identification of STN records implemented
NEWS	6	Jul 21	Polymer class term count added to REGISTRY
NEWS	7	Jul 22	INPADOC: Basic index (/BI) enhanced; Simultaneous Left and Right Truncation available
NEWS	8	AUG 05	New pricing for EUROPATFULL and PCTFULL effective August 1, 2003
NEWS	9	AUG 13	Field Availability (/FA) field enhanced in BEILSTEIN
NEWS	10	AUG 15	PATDPAFULL: one FREE connect hour, per account, in September 2003
NEWS	11	AUG 15	PCTGEN: one FREE connect hour, per account, in September 2003
NEWS	12	AUG 15	RDISCLOSURE: one FREE connect hour, per account, in September 2003
NEWS	13	AUG 15	TEMA: one FREE connect hour, per account, in September 2003
NEWS	14	AUG 18	Data available for download as a PDF in RDISCLOSURE
NEWS	15	AUG 18	Simultaneous left and right truncation added to PASCAL
NEWS	16	AUG 18	FROSTI and KOSMET enhanced with Simultaneous Left and Righ Truncation
NEWS	17	AUG 18	Simultaneous left and right truncation added to ANABSTR
NEWS	18	SEP 22	DIPPR file reloaded

NEWS EXPRESS	April 4 CURRENT WINDOWS VERSION IS V6.01a, CURRENT MACINTOSH VERSION IS V6.0b(ENG) AND V6.0Jb(JP), AND CURRENT DISCOVER FILE IS DATED 01 APRIL 2003
NEWS HOURS	STN Operating Hours Plus Help Desk Availability
NEWS INTER	General Internet Information
NEWS LOGIN	Welcome Banner and News Items
NEWS PHONE	Direct Dial and Telecommunication Network Access to STN
NEWS WWW	CAS World Wide Web Site (general information)

Enter NEWS followed by the item number or name to see news on that specific topic.

Kamal Saeed

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* * * * * * * * * * * * * * STN Columbus * * * * * * * * * * * * * * * *

FILE 'HOME' ENTERED AT 08:21:14 ON 24 SEP 2003

=> file reg
COST IN U.S. DOLLARS

	SINCE FILE ENTRY	TOTAL SESSION
FULL ESTIMATED COST	0.21	0.21

FILE 'REGISTRY' ENTERED AT 08:21:23 ON 24 SEP 2003
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Property values tagged with IC are from the ZIC/VINITI data file
provided by InfoChem.

STRUCTURE FILE UPDATES: 22 SEP 2003 HIGHEST RN 591204-55-6
DICTIONARY FILE UPDATES: 22 SEP 2003 HIGHEST RN 591204-55-6

TSCA INFORMATION NOW CURRENT THROUGH JULY 14, 2003

Please note that search-term pricing does apply when
conducting SmartSELECT searches.

Crossover limits have been increased. See HELP CROSSOVER for details.

Experimental and calculated property data are now available. See HELP
PROPERTIES for more information. See STNote 27, Searching Properties
in the CAS Registry File, for complete details:
http://www.cas.org/ONLINE/STN/STNOTES/stnotes27.pdf

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L1 STRUCTURE UPLOADED

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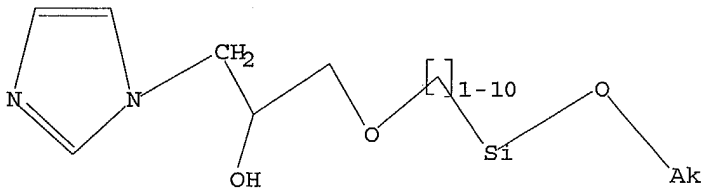
L1 HAS NO ANSWERS
L1 STR



Structure attributes must be viewed using STN Express query preparation.

=> s l1 full
FULL SEARCH INITIATED 08:21:51 FILE 'REGISTRY'
FULL SCREEN SEARCH COMPLETED - 156 TO ITERATE

100.0% PROCESSED 156 ITERATIONS 56 ANSWERS
SEARCH TIME: 00.00.01

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09936073 24/09/2003

L2 56 SEA SSS FUL L1

=> file caplus

COST IN U.S. DOLLARS	SINCE FILE ENTRY	TOTAL SESSION
FULL ESTIMATED COST	148.15	148.36

FILE 'CAPLUS' ENTERED AT 08:21:58 ON 24 SEP 2003
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PLEASE SEE "HELP USAGETERMS" FOR DETAILS.

FILE COVERS 1907 - 24 Sep 2003 VOL 139 ISS 13
FILE LAST UPDATED: 23 Sep 2003 (20030923/ED)

This file contains CAS Registry Numbers for easy and accurate substance identification.

=> s l2
L3 33 L2

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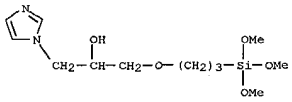
Kamal Saeed

L3 ANSWER 1 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN
ACCESSION NUMBER: 2003:693359 CAPLUS
TITLE: Epoxy resin compositions with good reflow crack resistance and one-side-sealed semiconductor devices
INVENTOR(S): Sugiyama, Hiroshi; Toyama, Takashi
PATENT ASSIGNEE(S): Matsushita Electric Works, Ltd., Japan
SOURCE: Jpn. Kokai Tokkyo Koho, 10 pp.
CODEN: JKXXAF
DOCUMENT TYPE: Patent
LANGUAGE: Japanese
FAMILY ACC. NUM. COUNT: 1
PATENT INFORMATION:

PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
JP 2003246839	A2	20030905	JP 2002-48773	20020225

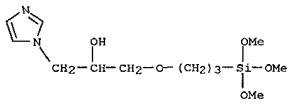
PRIORITY APPLN. INFO.: JP 2002-48773 20020225
AB The compns. comprise (a) epoxy resins contg. XCR2R3-1,4-C6H4CR4R5X (I; X = 3-R1-4-GO-substituted Ph; G = glycidyl; R1-R5 = H, Me, tert-Bu) and/or GO-1,4-C6H4CMe2-1,4-C6H4CMeZ2 (Z = 4-GO-substituted Ph), (b) crosslinking agents contg. phenol novolak HOC6H4[CH2C6H3(OH)]mCH2C6H4OH (II; m .gtoreq.0) with II (m = 0) content .ltoreq.10%, (c) crosslinking accelerators, and (d) inorg. fillers. Thus, a compn. contg. I (R1-R5 = Me) 7.8, DL 92 (II) 4, a reaction product of tetraphenylphosphonium tetraphenylborate and II 0.3, and fused silica 86 parts was transfer-molded to give a test piece showing Tg 198.degree., low warpage, and shrinkage at molding (JIS K 6911) 0.08%.
IT **149394-70-7**
RL: MOA (Modifier or additive use); TEM (Technical or engineered material use); USES (Uses)
(epoxy resin compns. with good reflow crack resistance for one-side-sealed semiconductor devices)
RN 149394-70-7 CAPLUS
CN 1H-Imidazole-1-ethanol, .alpha.-[[3-(trimethoxysilyl)propoxy]methyl]- (9CI) (CA INDEX NAME)



L3 ANSWER 2 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN
ACCESSION NUMBER: 2003:219344 CAPLUS
DOCUMENT NUMBER: 138:257832
TITLE: Secondary lithium battery
INVENTOR(S): Tajime, Ryoich; Kumagaya, Masashi
PATENT ASSIGNEE(S): Japan Energy Corp., Japan; Kashima Oil Co., Ltd.; Nikko Materials Co., Ltd.; Petoca Materials Ltd.
SOURCE: Jpn. Kokai Tokkyo Koho, 7 pp.
CODEN: JKXXAF
DOCUMENT TYPE: Patent
LANGUAGE: Japanese
FAMILY ACC. NUM. COUNT: 1
PATENT INFORMATION:

PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
JP 2003086185	A2	20030320	JP 2001-272213	20010907

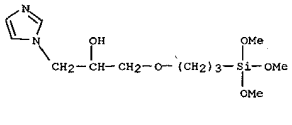
PRIORITY APPLN. INFO.: JP 2001-272213 20010907
AB The battery has an anode contg. a Li-intercalating active mass, a cathode, and an electrolyte; where the anode contains a imidazole silane compd.
IT **149394-70-7**
RL: DEV (Device component use); USES (Uses)
(anodes contg. imidazole silane compds. for secondary lithium batteries)
RN 149394-70-7 CAPLUS
CN 1H-Imidazole-1-ethanol, .alpha.-[[3-(trimethoxysilyl)propoxy]methyl]- (9CI) (CA INDEX NAME)



L3 ANSWER 3 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN
ACCESSION NUMBER: 2003:132664 CAPLUS
DOCUMENT NUMBER: 138:179310
TITLE: Paper sheet made of fluoropolymer fiber, copper-clad board using the paper sheet for printed circuit, and manufacture of board
INVENTOR(S): Suzuki, Takanori; Tsuda, Osamu
PATENT ASSIGNEE(S): Tomoegawa Paper Co., Ltd., Japan
SOURCE: Jpn. Kokai Tokkyo Koho, 8 pp.
CODEN: JKXXAF
DOCUMENT TYPE: Patent
LANGUAGE: Japanese
FAMILY ACC. NUM. COUNT: 1
PATENT INFORMATION:

PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
JP 2003049387	A2	20030221	JP 2001-234365	20010802

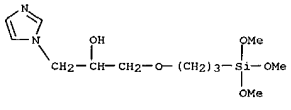
PRIORITY APPLN. INFO.: JP 2001-234365 20010802
AB The porous sheet is that obtained by paper-making wet process of a slurry contg. fluoropolymer fibers optionally assocd. with inorg. fibers and/or inorg. particles followed by firing, which has av. pore size 1-50 .mu.m and max. pore size .ltoreq.250 .mu.m. The board consists of the paper sheet and a Cu foil with 10-point av. surface roughness Rz 0.5-8.0 .mu.m, which are laminated and hot pressed in vacuo in the claimed manufg. process. The board, showing improved adhesion between the fluoropolymer fiber paper and the Cu foil, provides a printed circuit board requiring low dielec. loss tangent.
IT **149394-70-7**, IS 1000
RL: MOA (Modifier or additive use); USES (Uses)
(couplers; for porous paper sheet made of fluoropolymer fiber for copper-clad printed circuit board)
RN 149394-70-7 CAPLUS
CN 1H-Imidazole-1-ethanol, .alpha.-[[3-(trimethoxysilyl)propoxy]methyl]- (9CI) (CA INDEX NAME)



L3 ANSWER 4 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN
ACCESSION NUMBER: 2002:921414 CAPLUS
DOCUMENT NUMBER: 138:5357
TITLE: Prepreg made of epoxy resin-impregnated organic fiber substrate and laminated board
INVENTOR(S): Ishida, Takehiro; Takada, Toshiharu
PATENT ASSIGNEE(S): Matsushita Electric Works, Ltd., Japan
SOURCE: Jpn. Kokai Tokkyo Koho, 6 pp.
CODEN: JKXXAF
DOCUMENT TYPE: Patent
LANGUAGE: Japanese
FAMILY ACC. NUM. COUNT: 1
PATENT INFORMATION:

PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
JP 2002348392	A2	20021204	JP 2001-159105	20010528

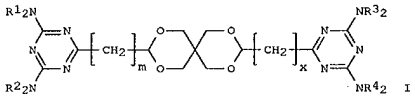
PRIORITY APPLN. INFO.: JP 2001-159105 20010528
AB The prepreg is that obtained by impregnation of an org. fiber substrate with a compn. of a P-contg. epoxy resin, a hardener for epoxy resin, and a imdazolesilane as a surface treatment. The laminated board, preferably a metal-clad laminated board as printed circuit board with fire resistance and good laser processability (compared with prepregs using glass fibers), is that prepd. by hot pressing of the prepreg. Thus, 9,10-dihydro-9-oxa-10-phosphaphenanthrene (HCA) and cresol novolak epoxy resin (YDCN 701) were reacted to give P-contg. epoxy resin, 100 parts of which was mixed with 39 parts bisphenol A novolak resin (Epicure YLH 129) and 1.0 part imidazolesilane (IS 1000) and dissolved in MEK to give a varnish. Then, all arom. aramid nonwoven fabrics were impregnated with the varnish to give the prepregs, 8 of which were laminated, sandwiched between a pair of Cu foils, and hot-pressed to give a Cu-clad laminated board showing UL-94 flame retardance V-0 and blister in heating to 270.degree..
IT **149394-70-7**, IS 1000
RL: MOA (Modifier or additive use); USES (Uses)
(surface treatment; in prepreg made of epoxy resin-impregnated org. fiber substrate for laminated printed circuit board)
RN 149394-70-7 CAPLUS
CN 1H-Imidazole-1-ethanol, .alpha.-[[3-(trimethoxysilyl)propoxy]methyl]- (9CI) (CA INDEX NAME)



L3 ANSWER 5 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN
ACCESSION NUMBER: 2002:592037 CAPLUS
DOCUMENT NUMBER: 137:155781
TITLE: Epoxy resin compositions and optical semiconductor devices sealed with them
INVENTOR(S): Nakasuji, Ikuo; Yamanaka, Hiroshi
PATENT ASSIGNEE(S): Matsushita Electric Works, Ltd., Japan
SOURCE: Jpn. Kokai Tokkyo Koho, 10 pp.
CODEN: JKXXAF
DOCUMENT TYPE: Patent
LANGUAGE: Japanese
FAMILY ACC. NUM. COUNT: 1
PATENT INFORMATION:

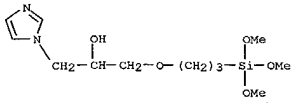
PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
JP 2002220512	A2	20020809	JP 2001-17712	20010126

PRIORITY APPLN. INFO.: JP 2001-17712 20010126
OTHER SOURCE(S): MARPAT 137:155781
GI



AB The compns., showing good adhesion to Pd- or Pd-Au-plated lead frames, contain epoxy resins (A), acid anhydride curing agents (B), mold-releasing agents (C), N compds. (D) selected from R2NC:NHNHC.tplbond.N (R = H, C1-10 hydrocarbyl), benzothiazole-2-thiol, 1H-benzimidazole-2-thiol, I (R1-4 = same as R; m, x = 1-10), R5R6NC:SSC:SNR7R8 (R5-8 = same as R), and YCH2CH(OH)CH2O(CH2)zSiR93-n(OR10)n [Y = C1-10 hydrocarbyl-(un)substituted 1-imidazolyl; R9,10 = C1-10 hydrocarbyl; n = 1-3; z = 1-10], and optionally SH-contg. Si compds. (E) HSR11SiR123-n'(OR13)n' (R11 = C1-10 hydrocarbylene; R12,13 = C1-10 hydrocarbyl; n' = 1-3). The semiconductor devices, (e.g., light-emitting diodes, laser diodes, photodiodes, phototransistors), sealed with the compns. show good light transmittance and moisture resistance.
IT **149394-70-7D**, derivs.
RL: MOA (Modifier or additive use); TEM (Technical or engineered material use); USES (Uses)
(epoxy resin compns. contg. acid anhydrides, N compds., and SH-contg. Si compds. for sealing optical semiconductor devices)
RN 149394-70-7 CAPLUS
CN 1H-Imidazole-1-ethanol, .alpha.-[[3-(trimethoxysilyl)propoxy]methyl]-(9CI) (CA INDEX NAME)

L3 ANSWER 5 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN (Continued)



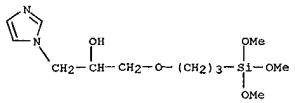
L3 ANSWER 6 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN
ACCESSION NUMBER: 2002:592036 CAPLUS
DOCUMENT NUMBER: 137:125891
TITLE: Epoxy potting composition for semiconductor device with good adhesion
INVENTOR(S): Sawai, Akito
PATENT ASSIGNEE(S): Matsushita Electric Works, Ltd., Japan
SOURCE: Jpn. Kokai Tokkyo Koho, 9 pp.
CODEN: JKXXAF
DOCUMENT TYPE: Patent
LANGUAGE: Japanese
FAMILY ACC. NUM. COUNT: 1
PATENT INFORMATION:

PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
JP 2002220511	A2	20020809	JP 2001-16461	20010125

PRIORITY APPLN. INFO.: JP 2001-16461 20010125
OTHER SOURCE(S): MARPAT 137:125891
GI

* STRUCTURE DIAGRAM TOO LARGE FOR DISPLAY - AVAILABLE VIA OFFLINE PRINT *

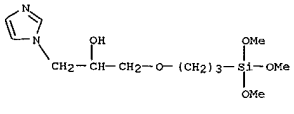
AB The compn. comprises an epoxy resin, a phenolic resin, a curing accelerator, an inorg. filler, a release agent, and an imidazole silane selected from I, II, and/or III (R1 = H, vinyl, C1-5 alkyl; R2 = H, C1-20 alkyl; R3, R4 = C1-3 alkyl; n = 1-3 integer). Thus, a compn. was made from a mixt. of ESCN 195XL 8.1, ESB 400T 1.3, FSM 6200 4.5, triphenylphosphine 0.1, Sb2O3 1.4, polyethylene wax 0.2, C black 0.2, cryst. SiO2 82, KBM 403 0.2, and IA 100 2.0%.
IT **149394-70-7**, IS 1000
RL: MOA (Modifier or additive use); USES (Uses)
(epoxy potting compn. for semiconductor device with good adhesion)
RN 149394-70-7 CAPLUS
CN 1H-Imidazole-1-ethanol, .alpha.-[[3-(trimethoxysilyl)propoxy]methyl]-(9CI) (CA INDEX NAME)



L3 ANSWER 7 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN
ACCESSION NUMBER: 2002:344954 CAPLUS
DOCUMENT NUMBER: 136:341854
TITLE: Epoxy resin compositions with good moisture resistance and adhesion to palladium and gold, and semiconductor devices sealed with them
INVENTOR(S): Shiraki, Hiroyuki; Nakamura, Masashi; Tsuji, Takayuki
PATENT ASSIGNEE(S): Matsushita Electric Works, Ltd., Japan
SOURCE: Jpn. Kokai Tokkyo Koho, 7 pp.
CODEN: JKXXAF
DOCUMENT TYPE: Patent
LANGUAGE: Japanese
FAMILY ACC. NUM. COUNT: 1
PATENT INFORMATION:

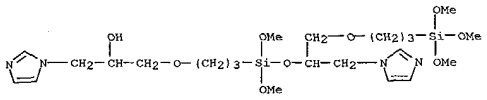
PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
JP 2002128872	A2	20020509	JP 2000-325000	20001025

PRIORITY APPLN. INFO.: JP 2000-325000 20001025
AB The compns. comprise epoxy resins, phenolic resins, inorg. fillers, and 0.001-2.0% imidazole silanes having no direct linkage between Si and N. Thus, a compn. comprising o-cresol-formaldehyde novolak epoxy resin (ESCN 195XL), dicyclopentadiene-phenol-based epoxy resin (HP 7200), aralkyl phenolic resin (HE 100), and imidazole silanes showed adhesion strength to Pd and Pd/Au, 11.0 and 10.3 MPa, resp., and good reflow resistance in packaging semiconductor devices.
IT **149394-70-7 149394-84-3 187463-05-4 187463-07-6**
RL: MOA (Modifier or additive use); TEM (Technical or engineered material use); USES (Uses)
(imidazole silane-contg. epoxy resin compns. with good moisture resistance and adhesion to Pd and Au for semiconductor devices packaging)
RN 149394-70-7 CAPLUS
CN 1H-Imidazole-1-ethanol, .alpha.-[[3-(trimethoxysilyl)propoxy]methyl]-(9CI) (CA INDEX NAME)

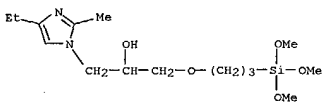


RN 149394-84-3 CAPLUS
CN 1H-Imidazole-1-ethanol, .alpha.-[8-(1H-imidazol-1-ylmethyl)-6,6,14,14-tetramethoxy-2,7,10,15-tetraoxa-6,14-disilahexadec-1-yl]- (9CI) (CA INDEX NAME)

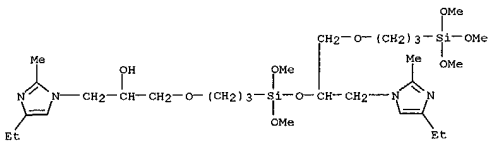
L3 ANSWER 7 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN (Continued)



RN 187463-05-4 CAPLUS
CN 1H-Imidazole-1-ethanol, 4-ethyl-2-methyl-.alpha.-[[3-(trimethoxysilyl)propoxy]methyl]- (9CI) (CA INDEX NAME)



RN 187463-07-6 CAPLUS
CN 1H-Imidazole-1-ethanol, 4-ethyl-.alpha.-[8-[(4-ethyl-2-methyl-1H-imidazol-1-yl)methyl]-6,6,14,14-tetramethoxy-2,7,10,15-tetraoxa-6,14-disilahexadec-1-yl]-2-methyl- (9CI) (CA INDEX NAME)



L3 ANSWER 8 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN
ACCESSION NUMBER: 2001:900692 CAPLUS
DOCUMENT NUMBER: 136:41233
TITLE: Surface treating agents of aluminum and aluminum alloy
for improving corrosion resistance and adhesion of coating films after painting
INVENTOR(S): Izumi, Koichiro; Nishimura, Satoshi; Tsuge, Kenji; Miyamoto, Satoshi
PATENT ASSIGNEE(S): Honda Motor Co., Ltd., Japan; Nippon Paint Co., Ltd.
SOURCE: Jpn. Kokai Tokkyo Koho, 6 pp.
CODEN: JKXXAF
DOCUMENT TYPE: Patent
LANGUAGE: Japanese
FAMILY ACC. NUM. COUNT: 1
PATENT INFORMATION:

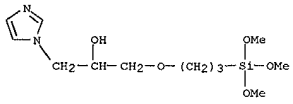
PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
JP 2001342578	A2	20011214	JP 2000-162585	20000531

PRIORITY APPLN. INFO.: JP 2000-162585 20000531

AB The surface treating agents contain a carboxyl group-contg. polymer 0.06-3, a Zr compd. 0.07-3.6 (as Zr), optionally substituted imidazole 0.03-2.4, amino-modified silicone 0.03-2.4, and optionally HF 0.01-1%. The Al and Al alloy are used for automobiles.

IT **149394-70-7**, IS-1000
RL: TEM (Technical or engineered material use); USES (Uses)
(surface treating agents of aluminum and aluminum alloy for improving corrosion resistance and adhesion of coating films after painting)

RN 149394-70-7 CAPLUS
CN 1H-Imidazole-1-ethanol, .alpha.-[[3-(trimethoxysilyl)propoxy]methyl]- (9CI) (CA INDEX NAME)



L3 ANSWER 9 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN
ACCESSION NUMBER: 2001:840573 CAPLUS
DOCUMENT NUMBER: 135:373067
TITLE: Coupling agent-containing anticorrosive epoxy composition for coating metal surface
INVENTOR(S): Tsuchida, Katsuyuki; Kumagaya, Masashi
PATENT ASSIGNEE(S): Nikko Materials Co., Ltd., Japan
SOURCE: Jpn. Kokai Tokkyo Koho, 6 pp.
CODEN: JKXXAF
DOCUMENT TYPE: Patent
LANGUAGE: Japanese
FAMILY ACC. NUM. COUNT: 1
PATENT INFORMATION:

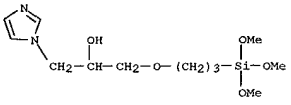
PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
JP 2001316835	A2	20011116	JP 2000-129547	20000428

PRIORITY APPLN. INFO.: JP 2000-129547 20000428

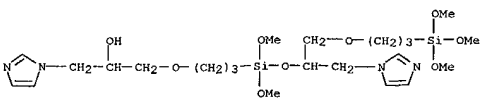
AB Title coating compn. comprises a reactive mixt. of epoxy resins and phosphoric compds. or esters and silane or titanium coupling agents. Thus, a galvanized steel plate was coated with a compn. comprising phosphoric acid-modified Epikote 828, 3.5, imidazole silanes 1, and melamine resin 3.5 parts, showing good anticorrosion.

IT **149394-70-7 149394-84-3**
RL: MOA (Modifier or additive use); USES (Uses)
(prepn. of coupling agent-contg. anticorrosive epoxy compn. for coating metal surface)

RN 149394-70-7 CAPLUS
CN 1H-Imidazole-1-ethanol, .alpha.-[[3-(trimethoxysilyl)propoxy]methyl]- (9CI) (CA INDEX NAME)



RN 149394-84-3 CAPLUS
CN 1H-Imidazole-1-ethanol, .alpha.-[8-(1H-imidazol-1-ylmethyl)-6,6,14,14-tetramethoxy-2,7,10,15-tetraoxa-6,14-disilahexadec-1-yl]- (9CI) (CA INDEX NAME)



L3 ANSWER 10 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN
ACCESSION NUMBER: 2001:763007 CAPLUS
DOCUMENT NUMBER: 135:319286
TITLE: Monocarboxylate salts of imidazole reaction products, process for preparing the salts, and surface treatments, additives for resins, and resin compositions, containing the same
INVENTOR(S): Kumagai, Masashi; Tsuchida, Katsuyuki
PATENT ASSIGNEE(S): Nikko Materials Co., Ltd., Japan
SOURCE: PCT Int. Appl., 23 pp.
CODEN: PIXXD2
DOCUMENT TYPE: Patent
LANGUAGE: Japanese
FAMILY ACC. NUM. COUNT: 1
PATENT INFORMATION:

PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
WO 2001077119	A1	20011018	WO 2001-JP819	20010206
W: CN, KR, US				
RW: AT, BE, CH, CY, DE, DK, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE, TR				
JP 2001348393	A2	20011218	JP 2000-226757	20000727
EP 1277757	A1	20030122	EP 2001-902777	20010206
R: AT, BE, CH, DE, DK, ES, FR, GB, GR, IT, LI, LU, NL, SE, MC, PT, IE, FI, CY, TR				
US 2003088108	A1	20030508	US 2001-936073	20010905

PRIORITY APPLN. INFO.: JP 2000-106274 A 20000407
JP 2000-226757 A 20000727
WO 2001-JP819 W 20010206

OTHER SOURCE(S): MARPAT 135:319286

AB Imidazoles react with glycidoxy-bearing silane compds. at 80.degree.-200.degree. and monocarboxylic acids at 50.degree.-200.degree. to prep. adhesion promoters. Thus, imidazole was added to the epoxy group of 3-glycidoxypropyltrimethoxysilane, used to form a salt with methacrylic acid. The salt improved adhesion of an epoxy resin to an Al alloy.

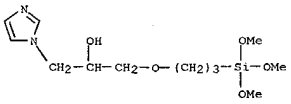
IT **367523-05-5P 367523-06-6P**
RL: IMF (Industrial manufacture); MOA (Modifier or additive use); PREP (Preparation); USES (Uses)
(monocarboxylate salts of imidazole reaction products for surface treatments and additives for resins)

RN 367523-05-5 CAPLUS
CN 2-Propenoic acid, 2-methyl-, compd. with .alpha.-[[3-(trimethoxysilyl)propoxy]methyl]-1H-imidazole-1-ethanol (1:1) (9CI) (CA INDEX NAME)

CM 1

CRN 149394-70-7
CMF C12 H24 N2 O5 Si

L3 ANSWER 10 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN (Continued)



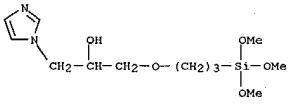
CM 2

CRN 79-41-4
CMF C4 H6 O2

RN 367523-06-6 CAPLUS
CN Hexadecanoic acid, compd. with .alpha.-[[3-(trimethoxysilyl)propoxy]methyl]-1H-imidazole-1-ethanol (1:1) (9CI) (CA INDEX NAME)

CM 1

CRN 149394-70-7
CMF C12 H24 N2 O5 Si

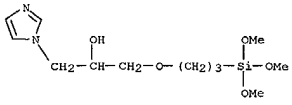


CM 2

CRN 57-10-3
CMF C16 H32 O2

IT **149394-70-7P**
RL: IMF (Industrial manufacture); RCT (Reactant); PREP (Preparation); RACT

L3 ANSWER 10 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN (Continued)
(Reactant or reagent)
(monocarboxylate salts of imidazole reaction products for surface treatments and additives for resins)
RN 149394-70-7 CAPLUS
CN 1H-Imidazole-1-ethanol, .alpha.-[[3-(trimethoxysilyl)propoxy]methyl]- (9CI) (CA INDEX NAME)

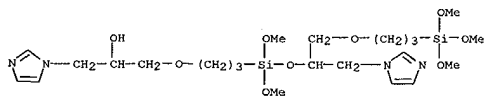


REFERENCE COUNT: 5 THERE ARE 5 CITED REFERENCES AVAILABLE FOR THIS RECORD. ALL CITATIONS AVAILABLE IN THE RE
FORMAT

L3 ANSWER 11 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN
ACCESSION NUMBER: 2001:717394 CAPLUS
DOCUMENT NUMBER: 135:274270
TITLE: The metal surface treatment solution containing silane
coupling agent and metals coated with the treatment solution
INVENTOR(S): Tsuchida, Katsuyuki; Kumagaya, Masashi
PATENT ASSIGNEE(S): Nikko Materials Co., Ltd., Japan
SOURCE: Jpn. Kokai Tokkyo Koho, 8 pp.
CODEN: JKXXAF
DOCUMENT TYPE: Patent
LANGUAGE: Japanese
FAMILY ACC. NUM. COUNT: 1
PATENT INFORMATION:

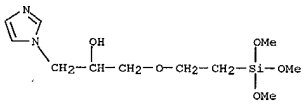
PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
JP 2001271185	A2	20011002	JP 2000-86427	20000327

PRIORITY APPLN. INFO.: JP 2000-86427 20000327
OTHER SOURCE(S): MARPAT 135:274270
AB An alk. corrosion inhibiting metal surface treatment soln. contains silicic acid, an amine and a silane deriv. selected from R1Si(OR2)nR33-n (R1 = hydrocarbyl group substituted with epoxy, vinyl, methacryl, amino, mercapto, imidazolyl, halo, styryl, or acryl groups; R2, R3 = C1-5 alkyl; R1-3 may contain ether bond) and Si(OR4)4 (R4 = C1-5 alkyl). The coating compn. may also contain water-sol. resins. Metals treated with the soln. exhibit excellent corrosion resistance and bonding with resin coatings.
IT **149394-84-3 364042-36-4**
RL: NUU (Other use, unclassified); USES (Uses)
(anticorrosive aq. coating compn. contg. silane coupling agents)
RN 149394-84-3 CAPLUS
CN 1H-Imidazole-1-ethanol, .alpha.-[8-(1H-imidazol-1-ylmethyl)-6,6,14,14-tetramethoxy-2,7,10,15-tetraoxa-6,14-disilahexadec-1-yl]- (9CI) (CA INDEX NAME)



RN 364042-36-4 CAPLUS
CN 1H-Imidazole-1-ethanol, .alpha.-[[2-(trimethoxysilyl)ethoxy]methyl]- (9CI) (CA INDEX NAME)

L3 ANSWER 11 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN (Continued)



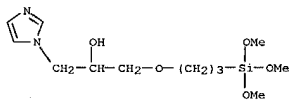
L3 ANSWER 12 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN
ACCESSION NUMBER: 2001:507896 CAPLUS
DOCUMENT NUMBER: 135:96160
TITLE: Method for metal plating, pre-treating agent, and semiconductor wafer and semiconductor device using the same
INVENTOR(S): Imori, Toru; Kumagaya, Masashi; Sekiguchi, Junnosuke
PATENT ASSIGNEE(S): Nikko Materials Co., Ltd., Japan
SOURCE: PCT Int. Appl., 23 pp.
CODEN: PIXXD2
DOCUMENT TYPE: Patent
LANGUAGE: Japanese
FAMILY ACC. NUM. COUNT: 1
PATENT INFORMATION:

PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
WO 2001049898	A1	20010712	WO 2000-JP8166	20001120
W: CN, JP, KR, US				
RW: DE, FR, GB, IT				

PRIORITY APPLN. INFO.: JP 2000-1645 A 20000107
JP 2000-238047 A 20000807

AB A method for metal plating which comprises admixing or reacting a noble metal compd. as a catalyst with a silane coupling agent contg. a functional group having the capability of capturing a metal, to thereby prep. a pre-treating agent, subjecting an article to be treated to the surface treatment with the pre-treating agent, and then subjecting the pre-treated article to electroless plating. The method permits the prepn. without fail of metal-plated products also from a powder, a resin cloth and an article having a mirror surface such as a semiconductor wafer, which have been difficult to be metal-plated conventionally. Moreover, the employment of the method in fine wiring on the surface of a semiconductor wafer leads to the satisfactory coverage of a seed layer onto the inner wall of a via trench. As the silane coupling agent, a compd. having an azole group, in particular, imidazole group is suitably used.

IT **149394-70-7**
RL: NUU (Other use, unclassified); USES (Uses)
(coupling agent; method for metal plating, pre-treating agent, and semiconductor wafer and semiconductor device using the same)
RN 149394-70-7 CAPLUS
CN 1H-Imidazole-1-ethanol, .alpha.-[[3-(trimethoxysilyl)propoxy]methyl]- (9CI) (CA INDEX NAME)



L3 ANSWER 12 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN (Continued)
REFERENCE COUNT: 12 THERE ARE 12 CITED REFERENCES AVAILABLE FOR THIS
RECORD. ALL CITATIONS AVAILABLE IN THE RE FORMAT

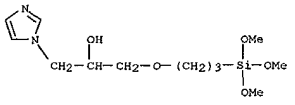
L3 ANSWER 13 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN
ACCESSION NUMBER: 2001:495296 CAPLUS
DOCUMENT NUMBER: 135:93601
TITLE: Silane additives, storage-stable epoxy resin compositions containing them with excellent curability, and their use
INVENTOR(S): Tsuchida, Katsuyuki; Kumagaya, Masashi
PATENT ASSIGNEE(S): Nikko Materials Co., Ltd., Japan
SOURCE: Jpn. Kokai Tokkyo Koho, 7 pp.
CODEN: JKXXAF
DOCUMENT TYPE: Patent
LANGUAGE: Japanese
FAMILY ACC. NUM. COUNT: 1
PATENT INFORMATION:

PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
JP 2001187836	A2	20010710	JP 2001-39712	20010216

PRIORITY APPLN. INFO.: JP 2001-39712 20010216
OTHER SOURCE(S): MARPAT 135:93601

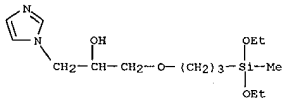
AB The additives, useful for sealants, resists, coatings, primers, and printed circuit boards, are QCH2CH(OH)CH2OCH2CH2CH2Si(OR3)2R4 (I; Q = 2-R1-4-R2-imidazolyl-1-yl; R1 = H, vinyl, C1-5 alkyl; R2 = H, C1-20 alkyl; R3,4 = C1-3 alkyl) or Me2NCH2CH(OH)CH2OCH2CH2CH2Si(OR3)2R4 (R3,4 = same as above). Thus, 2 sheets of A 2024P (Al alloy plate) were laminated via a 100:5:1:1 mixt. of Epikote 828 (bisphenol A epoxy resin), AH 154 (dicyandiamide), 2-methyl-4-methylimidazole, and I (R1,2 = H; R3 = Et; R4 = Me) to give a test piece with shear strength 1.13 kN/cm2.

IT **149394-70-7 348077-93-0**
RL: MOA (Modifier or additive use); USES (Uses)
(storage-stable epoxy resin compns. contg. imidazol- or dimethylamino-contg. silane additives for sealants, resists, coatings, and printed circuit boards)
RN 149394-70-7 CAPLUS
CN 1H-Imidazole-1-ethanol, .alpha.-[[3-(trimethoxysilyl)propoxy]methyl]- (9CI) (CA INDEX NAME)



RN 348077-93-0 CAPLUS
CN 1H-Imidazole-1-ethanol, .alpha.-[[3-(diethoxymethylsilyl)propoxy]methyl]- (9CI) (CA INDEX NAME)

L3 ANSWER 13 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN (Continued)

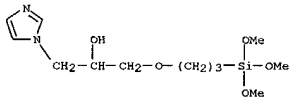


L3 ANSWER 14 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN
ACCESSION NUMBER: 2000:385771 CAPLUS
DOCUMENT NUMBER: 133:322674
TITLE: Improved adhesion between polyimide film and copper metal
AUTHOR(S): Inagaki, Norihiro; Tasaka, Shigeru; Sobukawa, Tadashi; Tamura, Katsuhiro
CORPORATE SOURCE: Faculty of Engineering, Shizuoka University, Japan
SOURCE: Koen Yoshishu - Nippon Setchaku Gakkai Nenji Taikai (1999), 37th, 45-48
CODEN: KYNTFX
PUBLISHER: Nippon Setchaku Gakkai
DOCUMENT TYPE: Journal
LANGUAGE: Japanese

AB Polyimide film (Kapton 200H) surface-modified by vinylimidazole plasma graft polymn. or silane coupling reaction with 1-[2-hydroxy-3-[3-(trimethoxysilyl)propyl]]-1,3-diazole showed improved adhesion to Cu, and the contribution of the imidazole group introduced into the polyimide surface to the adhesive strength improvement is large.

IT **149394-70-7**
RL: MOA (Modifier or additive use); USES (Uses)
(improved adhesion between polyimide film and copper metal)

RN 149394-70-7 CAPLUS
CN 1H-Imidazole-1-ethanol, .alpha.-[[3-(trimethoxysilyl)propoxy]methyl]- (9CI) (CA INDEX NAME)



L3 ANSWER 15 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN
ACCESSION NUMBER: 2000:376949 CAPLUS
DOCUMENT NUMBER: 133:5927
TITLE: Anticorrosive coating compositions and corrosion-resistant metal sheets coated therewith
INVENTOR(S): Akutsu, Yoshinori
PATENT ASSIGNEE(S): Japan Energy K. K., Japan
SOURCE: Jpn. Kokai Tokkyo Koho, 6 pp.
CODEN: JKXXAF
DOCUMENT TYPE: Patent
LANGUAGE: Japanese
FAMILY ACC. NUM. COUNT: 1
PATENT INFORMATION:

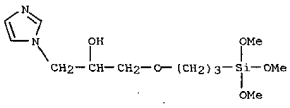
PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
JP 2000154349	A2	20000606	JP 1998-331107	19981120

PRIORITY APPLN. INFO.: JP 1998-331107 19981120
OTHER SOURCE(S): MARPAT 133:5927

AB The compns. with excellent adhesion to metal sheets comprise (A) organosilicon compds. having imidazole and alkoxysilyl groups, (B) epoxy resins having .gtoreq.2 epoxy groups in a mol., and (C) organosilicon compds. having 3 carbonyl and alkoxysilyl groups, or (D) H2O-insol. organosilicon compds. having 2 alkoxysilyl groups. Thus, Epikote 828 10, an imidazole-contg. alkoxysilane compd. mixt. 1, salicylic acid 0.6, and AcCH[CO(CH2)10Si(OMe)3]CO2(CH2)nSi(OMe)3 2 parts were dissolved in MeOH to give a compn., which was applied on an Al sheet and baked to form a coating showing excellent adhesion and corrosion resistance.

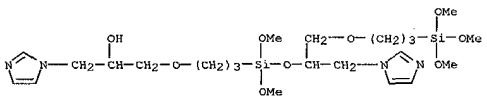
IT **149394-70-7 149394-84-3**
RL: PRP (Properties); TEM (Technical or engineered material use); USES (Uses)
(epoxy resin-alkoxysilane anticorrosive coating compns. with good adhesion to metals)

RN 149394-70-7 CAPLUS
CN 1H-Imidazole-1-ethanol, .alpha.-[[3-(trimethoxysilyl)propoxy]methyl]- (9CI) (CA INDEX NAME)



RN 149394-84-3 CAPLUS
CN 1H-Imidazole-1-ethanol, .alpha.-[8-(1H-imidazol-1-ylmethyl)-6,6,14,14-tetramethoxy-2,7,10,15-tetraoxa-6,14-disilahexadec-1-yl]- (9CI) (CA INDEX NAME)

L3 ANSWER 15 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN (Continued)



L3 ANSWER 16 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN
ACCESSION NUMBER: 2000:317083 CAPLUS
DOCUMENT NUMBER: 132:335873
TITLE: Epoxy resin-based alkoxy silane-containing anticorrosive coating compositions
INVENTOR(S): Akutsu, Yoshitoku; Kiheida, Yukinori
PATENT ASSIGNEE(S): Japan Energy K. K., Japan
SOURCE: Jpn. Kokai Tokkyo Koho, 5 pp.
CODEN: JKXXAF
DOCUMENT TYPE: Patent
LANGUAGE: Japanese
FAMILY ACC. NUM. COUNT: 1
PATENT INFORMATION:

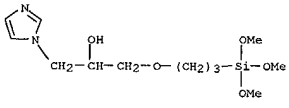
PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
JP 2000136344	A2	20000516	JP 1998-311016	19981030
JP 3335932	B2	20021021		

PRIORITY APPLN. INFO.: JP 1998-311016 19981030

AB The title compns., useful for refinery plants, tanks, bridges, etc. (no data), comprise epoxy resins (e.g., Epikote 828), amine hardeners (e.g., diaminodicyclohexylmethane), fillers (e.g., silica), and alkoxy silanes (e.g., tetramethoxysilane, IS-1000, LS-3750).

IT **149394-70-7**, IS-1000
RL: PRP (Properties); TEM (Technical or engineered material use); USES (Uses)
(IS-1000, coupling agents; epoxy resin-based alkoxy silane-contg. anticorrosive coating compns.)

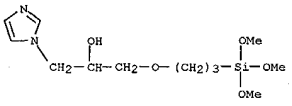
RN 149394-70-7 CAPLUS
CN 1H-Imidazole-1-ethanol, .alpha.-[[3-(trimethoxysilyl)propoxy]methyl]- (9CI) (CA INDEX NAME)



L3 ANSWER 17 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN
ACCESSION NUMBER: 1999:433076 CAPLUS
DOCUMENT NUMBER: 131:200910
TITLE: Improved adhesion between Kapton film and copper metal
by silane-coupling reactions
AUTHOR(S): Inagaki, N.; Tasaka, S.; Onodera, A.
CORPORATE SOURCE: Laboratory of Polymer Chemistry, Faculty of Engineering, Shizuoka University, Hamamatsu, 432-8561,
Japan
SOURCE: Journal of Applied Polymer Science (1999), 73(9), 1645-1654
CODEN: JAPNAB; ISSN: 0021-8995
PUBLISHER: John Wiley & Sons, Inc.
DOCUMENT TYPE: Journal
LANGUAGE: English

AB Kapton film, poly[(N,N'-oxydiphenylene)pyromellitimide], was modified by silane-coupling reactions using 3'-(trimethoxysilyl)propoxy-2-hydroxypropyl-1,3-diazole (Si-imidazole) to improve the adhesion with copper metal. The Kapton film surface was first treated with argon plasma for 30 s, then dipped into a methanol soln. of Si-imidazole (0.01 wt. %), followed by heating at 110.degree.C for 90 min. The Kapton surfaces, modified by the argon plasma and Si-imidazole coupling reactions, were analyzed by water contact-angle measurement, at. force microscopy, and XPS. The Si-imidazole modification showed a large increase in adhesion between the copper metal and the Kapton film. The peel strength of the copper metal/Kapton film joint increased from 0.94 to 2.4 N/5 mm. The failure occurred at the interface between the Si-imidazole and the Kapton film layer. We conclude that the Si-imidazole modification is an effective treatment for improvement of the adhesion between copper metal and Kapton film.

IT **149394-70-7**
RL: MOA (Modifier or additive use); RCT (Reactant); RACT (Reactant or reagent); USES (Uses)
(surface modifier; improved adhesion between Kapton film and copper metal by silane-coupling reactions)
RN 149394-70-7 CAPLUS
CN 1H-Imidazole-1-ethanol, .alpha.-[[3-(trimethoxysilyl)propoxy]methyl]- (9CI) (CA INDEX NAME)



REFERENCE COUNT: 10 THERE ARE 10 CITED REFERENCES AVAILABLE FOR THIS
RECORD. ALL CITATIONS AVAILABLE IN THE RE FORMAT

L3 ANSWER 17 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN (Continued)

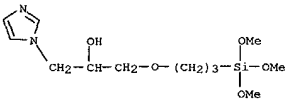
L3 ANSWER 18 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN
ACCESSION NUMBER: 1999:78681 CAPLUS
DOCUMENT NUMBER: 130:161885
TITLE: Manufacture of polyimide-metal composite thin film
INVENTOR(S): Suzuki, Takanori
PATENT ASSIGNEE(S): Tomoegawa Paper Co., Ltd., Japan
SOURCE: Jpn. Kokai Tokkyo Koho, 6 pp.
CODEN: JKXXAF
DOCUMENT TYPE: Patent
LANGUAGE: Japanese
FAMILY ACC. NUM. COUNT: 1
PATENT INFORMATION:

PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
JP 11029852	A2	19990202	JP 1997-205349	19970714
JP 3331153	B2	20021007		

PRIORITY APPLN. INFO.: JP 1997-205349 19970714

AB The manuf. method involves (1) plasma treating a polyimide film surface, (2) treating the film with an imidazole group-contg. silane coupling agent, and (3) forming a metal thin film on the polyimide film by sputtering or deposition. The film shows good adhesion.

IT **149394-70-7**, IS 1000
RL: NUU (Other use, unclassified); USES (Uses)
(treatment by plasma and coupling agent in manuf. of polyimide-metal composite film)
RN 149394-70-7 CAPLUS
CN 1H-Imidazole-1-ethanol, .alpha.-[[3-(trimethoxysilyl)propoxy]methyl]- (9CI) (CA INDEX NAME)



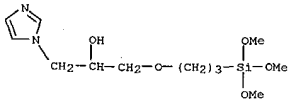
L3 ANSWER 19 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN
ACCESSION NUMBER: 1998:768318 CAPLUS
DOCUMENT NUMBER: 130:74947
TITLE: Copper foil for printed circuit board
INVENTOR(S): Tsuchida, Katsuyuki; Kumagaya, Masashi; Okazaki, Yoshinori
PATENT ASSIGNEE(S): Japan Energy K. K., Japan; Nikko Gould Foil K. K.
SOURCE: Jpn. Kokai Tokkyo Koho, 15 pp.
CODEN: JKXXAF
DOCUMENT TYPE: Patent
LANGUAGE: Japanese
FAMILY ACC. NUM. COUNT: 1
PATENT INFORMATION:

PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
JP 10317159	A2	19981202	JP 1997-147070	19970522

PRIORITY APPLN. INFO.: JP 1997-147070 19970522

AB The foil has coating of coupling agent having .gtoreq.1 functional groups selected from imidazole, dialkylamino, and pyridine at least on its roughened surface. The foil may have siloxane layer beneath the coupling agent layer. The foil shows strong adhesion with polymer.

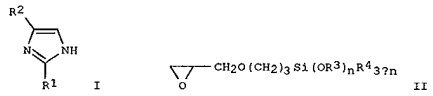
IT **149394-70-7**
RL: DEV (Device component use); USES (Uses)
(coupling agent; copper foil having coupling agent coatings for stronger adhesion with polymer for printed circuit board)
RN 149394-70-7 CAPLUS
CN 1H-Imidazole-1-ethanol, .alpha.-[[3-(trimethoxysilyl)propoxy]methyl]- (9CI) (CA INDEX NAME)



L3 ANSWER 20 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN
ACCESSION NUMBER: 1998:455475 CAPLUS
DOCUMENT NUMBER: 129:168105
TITLE: Photosensitive resin composition containing imidazolesilane compound and photosensitive element using same
INVENTOR(S): Ichikawa, Tatsuya; Tanaka, Yoji; Chiba, Tatsuo; Tsuchita, Katsushi; Kumagaya, Masashi
PATENT ASSIGNEE(S): Hitachi Chemical Co., Ltd., Japan; Japan Energy K. K.
SOURCE: Jpn. Kokai Tokkyo Koho, 7 pp.
CODEN: JKXXAF
DOCUMENT TYPE: Patent
LANGUAGE: Japanese
FAMILY ACC. NUM. COUNT: 1
PATENT INFORMATION:

PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
JP 10186657	A2	19980714	JP 1996-349441	19961227
PRIORITY APPLN. INFO.:			JP 1996-349441	19961227

OTHER SOURCE(S): MARPAT 129:168105
GI



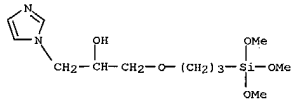
I II

AB The title compn. contains (a) a carboxyl group-contg. binder polymer, (b) a photopolymg. compd. having polymerizable ethylenic unsatd. bonds in its mol., (c) a photopolymn. initiator, and (d) an imidazolesilane compd. prepd. by reacting an imidazole compd. I (R1 = H or C1-20 alkyl; R2 = H, vinyl, C1-5 alkyl) with a silane compd. II (R3, R4 = C1-3 alkyl; n = 1-3) at 80-200.degree.. The photosensitive element comprises a support coated with a photosensitive layer made of the compn. and optionally laminated with a protective film. The compn. shows good adhesion to metallic substrates, resistance to plating, esp. Au-plating, and chem. resistance.

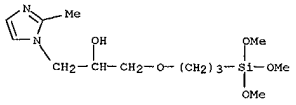
IT **149394-70-7P 149394-71-8P 149394-72-9P**
149394-73-0P 149394-84-3P 149394-85-4P
149394-86-5P 149394-87-6P
RL: MOA (Modifier or additive use); PNU (Preparation, unclassified); TEM (Technical or engineered material use); PREP (Preparation); USES (Uses)
(photosensitive resin compn. contg. imidazolesilane compd.)

RN 149394-70-7 CAPLUS
CN 1H-Imidazole-1-ethanol, .alpha.-[[3-(trimethoxysilyl)propoxy]methyl]- (9CI) (CA INDEX NAME)

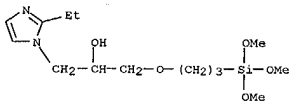
L3 ANSWER 20 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN (Continued)



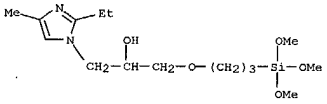
RN 149394-71-8 CAPLUS
CN 1H-Imidazole-1-ethanol, 2-methyl-.alpha.-[[3-(trimethoxysilyl)propoxy]methyl]- (9CI) (CA INDEX NAME)



RN 149394-72-9 CAPLUS
CN 1H-Imidazole-1-ethanol, 2-ethyl-.alpha.-[[3-(trimethoxysilyl)propoxy]methyl]- (9CI) (CA INDEX NAME)

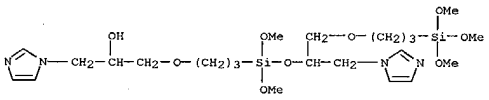


RN 149394-73-0 CAPLUS
CN 1H-Imidazole-1-ethanol, 2-ethyl-4-methyl-.alpha.-[[3-(trimethoxysilyl)propoxy]methyl]- (9CI) (CA INDEX NAME)

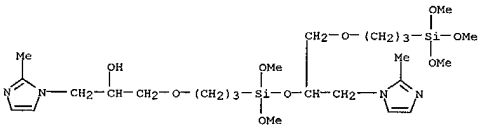


RN 149394-84-3 CAPLUS

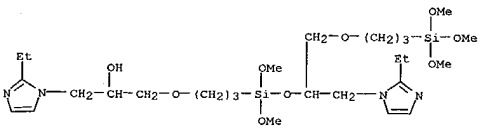
L3 ANSWER 20 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN (Continued)
CN 1H-Imidazole-1-ethanol, .alpha.-[8-(1H-imidazol-1-ylmethyl)-6,6,14,14-tetramethoxy-2,7,10,15-tetraoxa-6,14-disilahexadec-1-yl]- (9CI) (CA INDEX NAME)



RN 149394-85-4 CAPLUS
CN 1H-Imidazole-1-ethanol, 2-methyl-.alpha.-[6,6,14,14-tetramethoxy-8-[(2-methyl-1H-imidazol-1-yl)methyl]-2,7,10,15-tetraoxa-6,14-disilahexadec-1-yl]- (9CI) (CA INDEX NAME)

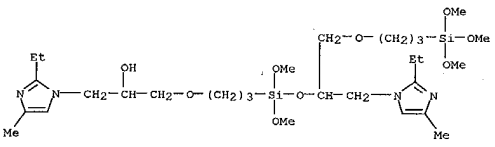


RN 149394-86-5 CAPLUS
CN 1H-Imidazole-1-ethanol, 2-ethyl-.alpha.-[8-[(2-ethyl-1H-imidazol-1-yl)methyl]-6,6,14,14-tetramethoxy-2,7,10,15-tetraoxa-6,14-disilahexadec-1-yl]- (9CI) (CA INDEX NAME)



RN 149394-87-6 CAPLUS
CN 1H-Imidazole-1-ethanol, 2-ethyl-.alpha.-[8-[(2-ethyl-4-methyl-1H-imidazol-1-yl)methyl]-6,6,14,14-tetramethoxy-2,7,10,15-tetraoxa-6,14-disilahexadec-1-yl]-4-methyl- (9CI) (CA INDEX NAME)

L3 ANSWER 20 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN (Continued)



L3 ANSWER 21 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN
ACCESSION NUMBER: 1998:407634 CAPLUS
DOCUMENT NUMBER: 129:123866
TITLE: Anticorrosive electrodeposition compositions with good adhesion to metals
INVENTOR(S): Akutsu, Yoshinori
PATENT ASSIGNEE(S): Japan Energy K. K., Japan
SOURCE: Jpn. Kokai Tokkyo Koho, 5 pp.
CODEN: JKXXAF
DOCUMENT TYPE: Patent
LANGUAGE: Japanese
FAMILY ACC. NUM. COUNT: 1
PATENT INFORMATION:

PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
JP 10168355	A2	19980623	JP 1996-326757	19961206

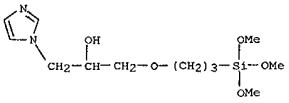
PRIORITY APPLN. INFO.: JP 1996-326757 19961206
OTHER SOURCE(S): MARPAT 129:123866
GI

* STRUCTURE DIAGRAM TOO LARGE FOR DISPLAY - AVAILABLE VIA OFFLINE PRINT *

AB Title aq. dispersion compns. contain imidazole silanes I, II, and/or III (R1 = H, vinyl, C1-5 alkyl; R2 = H, C1-20 alkyl; R3, R4 = C1-3 alkyl; n = 1-3) at a preferable amt. of 0.1-10%. A galvanized steel plate was electrodeposited with a mixt. of 500 parts 20% dimethylaminoethyl methacrylate-2-hydroxyethyl acrylate-Me acrylate-styrene-TDI copolymer acetate and 500 parts 2% 5:2:3 I/II/III (R1, R2 = H, R3 = Me, n = 3) blend and baked to form a 20-.mu.m film showing good adhesion to the steel plate initially and after 3 h in boiling water and good corrosion resistance.

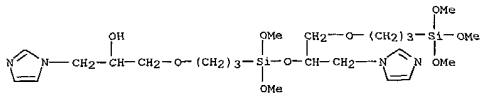
IT **149394-70-7 149394-84-3**
RL: MOA (Modifier or additive use); USES (Uses)
(imidazole silane-contg. electrodepositions with metal adhesion and anticorrosion improvement)

RN 149394-70-7 CAPLUS
CN 1H-Imidazole-1-ethanol, .alpha.-[[3-(trimethoxysilyl)propoxy]methyl]- (9CI) (CA INDEX NAME)



RN 149394-84-3 CAPLUS

L3 ANSWER 21 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN (Continued)
CN 1H-Imidazole-1-ethanol, .alpha.-[8-(1H-imidazol-1-ylmethyl)-6,6,14,14-tetramethoxy-2,7,10,15-tetraoxa-6,14-disilahexadec-1-yl]- (9CI) (CA INDEX NAME)



L3 ANSWER 22 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN
ACCESSION NUMBER: 1998:289617 CAPLUS
DOCUMENT NUMBER: 129:16125
TITLE: Preparation of storage-stable silicon-containing quaternary imidazolium salts, hardening of epoxy resins using them, and their uses
INVENTOR(S): Tsuchida, Katsuyuki; Kumagaya, Masashi
PATENT ASSIGNEE(S): Japan Energy K. K., Japan
SOURCE: Jpn. Kokai Tokkyo Koho, 22 pp.
CODEN: JKXXAF
DOCUMENT TYPE: Patent
LANGUAGE: Japanese
FAMILY ACC. NUM. COUNT: 1
PATENT INFORMATION:

PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
JP 10120690	A2	19980512	JP 1996-280877	19961023

PRIORITY APPLN. INFO.: JP 1996-280877 19961023
OTHER SOURCE(S): MARPAT 129:16125
GI

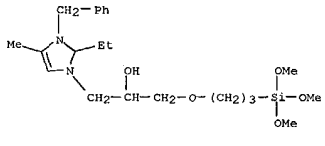
* STRUCTURE DIAGRAM TOO LARGE FOR DISPLAY - AVAILABLE VIA OFFLINE PRINT *

AB The imidazolium salts I [R1 = R3 = H, vinyl, C1-20 alkyl; R2 and R3 may be bonded to each other forming an arom ring; R4, R5 = C1-5 alkyl; R6 = H, C1-18 (un)substituted alkyl, alkenyl; X = halo, (in)org. acid residue; m = 1-10; n = 1-3], II, III, or IV are prepd. by treatment of imidazoles V with glycidyl compds. VI at 80-200.degree. and quaternization of the resulting products with R6X at 80-200.degree.. Epoxy resins are hardened using .gtoreq.1 selected from I, II, III, and IV and .gtoreq.1 anion acceptors selected from metal, metal carboxylates, metal-acetylacetone complexes, basic oxides, amphoteric oxides, metal carbonates, metal hydrides, and amines. Also claimed are hydrophilic surface treatment agents and antimicrobial agents contg. .gtoreq.1 selected from I, II, III, and IV. 3-Glycidoxypropyltrimethoxysilane was added dropwise to 2-ethyl-4-methylimidazole at 95.degree. over 30 min and the reaction mixt. was further stirred at 95.degree. for 1 h. Subsequently PhCH2Cl was added dropwise to the reaction mixt. at 140.degree. over 30 min and the reaction mixt. was stirred at 140.degree. for 1 h to give a mixt. of I (R1 = Et, R2 = R4 = Me, R3 = H, R6 = CH2Ph, m = n = 3, X = Cl), II, III, and IV (all variants are same as in I). Gel time of a contg. Epikote 828, the above imidazolium salt mixt., and Zn acetylacetonate was 3 min 33 s, vs. 59 s for a control compn. contg. 2-ethyl-4-methylimidazole as a hardening agent. Coating of an electrodeposited Cu foil with a MeOH soln. of the imidazolium salt mixt. made the surface hydrophilic. An imidazolium salt mixt. similarly prepd. from 2-undecylimidazole instead of 2-ethyl-4-methylimidazole inhibited growth of Aspergillus niger, Cladosporium resinae, etc.

IT **207732-47-6P 207732-56-7P 207732-60-3P**

L3 ANSWER 22 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN (Continued)
207732-62-5P 207732-66-9P 207732-68-1P
207732-70-5P 207732-73-8P 207732-75-0P
207732-77-2P 207732-80-7P 207732-82-9P
207732-84-1P 207732-88-5P 207732-90-9P
RL: BAC (Biological activity or effector, except adverse); BSU (Biological study, unclassified); BUU (Biological use, unclassified); IMF (Industrial manufacture); MOA (Modifier or additive use); SPN (Synthetic preparation); TEM (Technical or engineered material use); BIOL (Biological study); PREP (Preparation); USES (Uses)
(prepn. of storage-stable silicon-contg. quaternary imidazolium salts as epoxy resin hardeners, hydrophilic coatings, and microbicides)

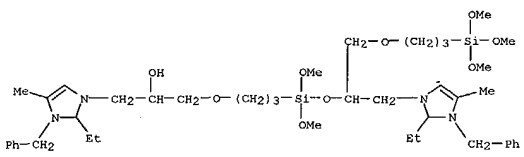
RN 207732-47-6 CAPLUS
CN 1H-Imidazolium, 2-ethyl-1-[2-hydroxy-3-[3-(trimethoxysilyl)propoxy]propyl]-4-methyl-3-(phenylmethyl)-, chloride (9CI) (CA INDEX NAME)



● Cl⁻

*** FRAGMENT DIAGRAM IS INCOMPLETE ***
RN 207732-56-7 CAPLUS
CN 1H-Imidazolium, 2-ethyl-1-[2-[[[3-[3-[2-ethyl-4-methyl-3-(phenylmethyl)-1H-imidazolium-1-yl]-2-hydroxypropoxy]propyl]dimethoxysilyl]oxy]-3-(3-(trimethoxysilyl)propoxy]propyl]-4-methyl-3-(phenylmethyl)-, dichloride (9CI) (CA INDEX NAME)

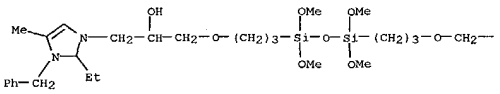
L3 ANSWER 22 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN (Continued)



●2 Cl⁻

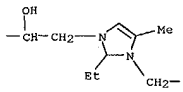
*** FRAGMENT DIAGRAM IS INCOMPLETE ***
RN 207732-60-3 CAPLUS
CN 1H-Imidazolium, 1,1'-[(1,1,3,3-tetramethoxy-1,3-disiloxanediyl)bis[3,1-propanediyloxy(2-hydroxy-3,1-propanediyl)]]bis[2-ethyl-4-methyl-3-(phenylmethyl)-, dichloride (9CI) (CA INDEX NAME)

PAGE 1-A



●2 Cl⁻

PAGE 1-B

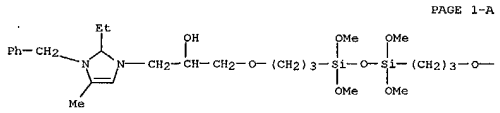


*** FRAGMENT DIAGRAM IS INCOMPLETE ***
RN 207732-62-5 CAPLUS
CN 1H-Imidazolium, 1-[2-hydroxy-3-[3-(trimethoxysilyl)propoxy]propyl]-2-methyl-3-(phenylmethyl)-, chloride (9CI) (CA INDEX NAME)

L3 ANSWER 22 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN (Continued)

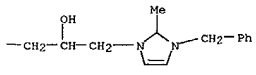
*** FRAGMENT DIAGRAM IS INCOMPLETE ***
RN 207732-68-1 CAPLUS
CN 1H-Imidazolium, 2-ethyl-1-[2-hydroxy-3-[3-[3-[3-[2-hydroxy-3-[2-methyl-3-(phenylmethyl)-1H-imidazolium-1-yl]propoxy]propyl]-1,1,3,3-tetramethoxydisiloxanyl]propoxy]propyl]-4-methyl-3-(phenylmethyl)-, dichloride (9CI) (CA INDEX NAME)

PAGE 1-A

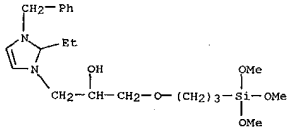


●2 Cl⁻

PAGE 1-B



*** FRAGMENT DIAGRAM IS INCOMPLETE ***
RN 207732-70-5 CAPLUS
CN 1H-Imidazolium, 2-ethyl-1-[2-hydroxy-3-[3-(trimethoxysilyl)propoxy]propyl]-3-(phenylmethyl)-, chloride (9CI) (CA INDEX NAME)

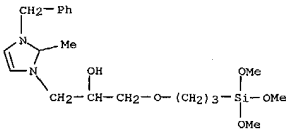


● Cl⁻

*** FRAGMENT DIAGRAM IS INCOMPLETE ***
RN 207732-73-8 CAPLUS
CN 1H-Imidazolium, 2-ethyl-1-[10-[[2-ethyl-3-(phenylmethyl)-1H-imidazolium-1-

Kamal Saeed

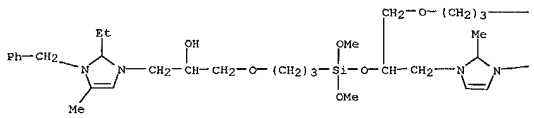
L3 ANSWER 22 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN (Continued)



● Cl⁻

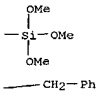
*** FRAGMENT DIAGRAM IS INCOMPLETE ***
RN 207732-66-9 CAPLUS
CN 1H-Imidazolium, 2-ethyl-1-[2-hydroxy-8,8,16,16-tetramethoxy-10-[[2-methyl-3-(phenylmethyl)-1H-imidazolium-1-yl]methyl]-4,9,12,17-tetraoxa-8,16-disilaoctadec-1-yl]-4-methyl-3-(phenylmethyl)-, dichloride (9CI) (CA INDEX NAME)

PAGE 1-A



●2 Cl⁻

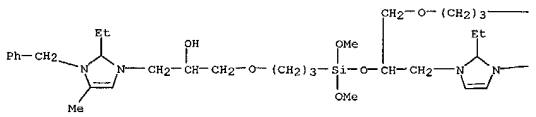
PAGE 1-B



L3 ANSWER 22 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN (Continued)

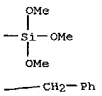
yl]methyl]-2-hydroxy-8,8,16,16-tetramethoxy-4,9,12,17-tetraoxa-8,16-disilaoctadec-1-yl]-4-methyl-3-(phenylmethyl)-, dichloride (9CI) (CA INDEX NAME)

PAGE 1-A



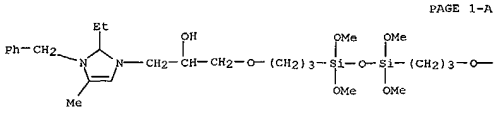
●2 Cl⁻

PAGE 1-B



*** FRAGMENT DIAGRAM IS INCOMPLETE ***
RN 207732-75-0 CAPLUS
CN 1H-Imidazolium, 2-ethyl-1-[3-[3-[3-[3-[3-[2-ethyl-3-(phenylmethyl)-1H-imidazolium-1-yl]-2-hydroxypropoxy]propyl]-1,1,3,3-tetramethoxydisiloxanyl]propoxy]-2-hydroxypropyl]-4-methyl-3-(phenylmethyl)-, dichloride (9CI) (CA INDEX NAME)

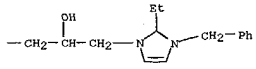
PAGE 1-A



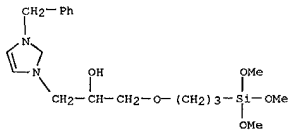
●2 Cl⁻

L3 ANSWER 22 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN (Continued)

PAGE 1-B



*** FRAGMENT DIAGRAM IS INCOMPLETE ***
RN 207732-77-2 CAPLUS
CN 1H-Imidazolium, 1-[2-hydroxy-3-[3-(trimethoxysilyl)propoxy]propyl]-3-(phenylmethyl)-, chloride (9CI) (CA INDEX NAME)

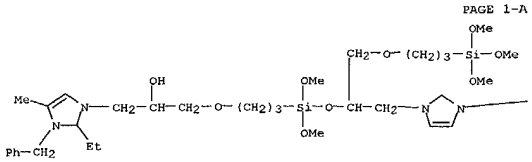


● Cl⁻

*** FRAGMENT DIAGRAM IS INCOMPLETE ***
RN 207732-80-7 CAPLUS
CN 1H-Imidazolium, 2-ethyl-1-[2-hydroxy-8,8,16,16-tetramethoxy-10-[[3-(phenylmethyl)-1H-imidazolium-1-yl]methyl]-4,9,12,17-tetraoxa-8,16-disilaoctadec-1-yl]-4-methyl-3-(phenylmethyl)-, dichloride (9CI) (CA INDEX NAME)

L3 ANSWER 22 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN (Continued)

PAGE 1-A

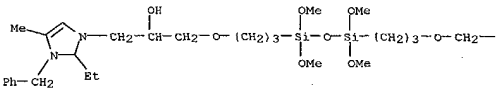


● 2 Cl⁻

PAGE 1-B

*** FRAGMENT DIAGRAM IS INCOMPLETE ***
RN 207732-82-9 CAPLUS
CN 1H-Imidazolium, 2-ethyl-1-[2-hydroxy-3-[3-[3-[3-[2-hydroxy-3-[3-(phenylmethyl)-1H-imidazolium-1-yl]propoxy]propyl]-1,1,3,3-tetramethoxydisiloxanyl]propoxy]propyl]-4-methyl-3-(phenylmethyl)-, dichloride (9CI) (CA INDEX NAME)

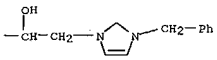
PAGE 1-A



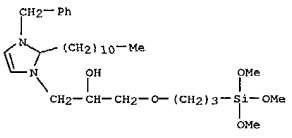
● 2 Cl⁻

L3 ANSWER 22 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN (Continued)

PAGE 1-B

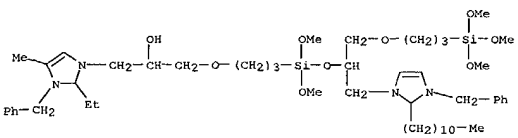


*** FRAGMENT DIAGRAM IS INCOMPLETE ***
RN 207732-84-1 CAPLUS
CN 1H-Imidazolium, 1-[2-hydroxy-3-[3-(trimethoxysilyl)propoxy]propyl]-3-(phenylmethyl)-2-undecyl-, chloride (9CI) (CA INDEX NAME)



● Cl⁻

*** FRAGMENT DIAGRAM IS INCOMPLETE ***
RN 207732-88-5 CAPLUS
CN 1H-Imidazolium, 2-ethyl-1-[2-hydroxy-8,8,16,16-tetramethoxy-10-[[3-(phenylmethyl)-2-undecyl-1H-imidazolium-1-yl]methyl]-4,9,12,17-tetraoxa-8,16-disilaoctadec-1-yl]-4-methyl-3-(phenylmethyl)-, dichloride (9CI) (CA INDEX NAME)

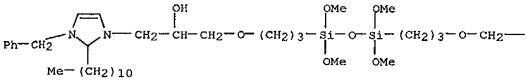


● 2 Cl⁻

*** FRAGMENT DIAGRAM IS INCOMPLETE ***
RN 207732-90-9 CAPLUS
CN 1H-Imidazolium, 2-ethyl-1-[2-hydroxy-3-[3-[3-[3-[2-hydroxy-3-[3-

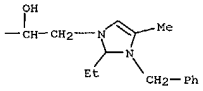
L3 ANSWER 22 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN (Continued)
(phenylmethyl)-2-undecyl-1H-imidazolium-1-yl]propoxy]propyl]-1,1,3,3-tetramethoxydisiloxanyl]propoxy]propyl]-4-methyl-3-(phenylmethyl)-, dichloride (9CI) (CA INDEX NAME)

PAGE 1-A



● 2 Cl⁻

PAGE 1-B



*** FRAGMENT DIAGRAM IS INCOMPLETE ***

L3 ANSWER 23 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN
ACCESSION NUMBER: 1998:227419 CAPLUS
DOCUMENT NUMBER: 128:309553
TITLE: Anticorrosive coating compositions for metals
INVENTOR(S): Tsuchita, Katsushi; Kumagaya, Masashi
PATENT ASSIGNEE(S): Japan Energy K. K., Japan
SOURCE: Jpn. Kokai Tokkyo Koho, 13 pp.
CODEN: JKXXAF
DOCUMENT TYPE: Patent
LANGUAGE: Japanese
FAMILY ACC. NUM. COUNT: 1
PATENT INFORMATION:

PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
JP 10095933	A2	19980414	JP 1996-254698	19960926
JP 3386959	B2	20030317		

PRIORITY APPLN. INFO.: JP 1996-254698 19960926

AB The compns. with improved adhesion contain silicic acid and optionally .gtoreq.1 organosilicon compds. selected from R1Si(OR2)nR33-n, R4Si(OR2)nR33-n, and Si(OR8)4 [R1 = hydrocarbyl substituted by epoxy, vinyl, (meth)acrylic, amino, SH, imidazole, halo, OH, and/or styryl group, may contain ether or ester link; R2, R3 = C1-5 alkyl, may contain ether link; n = 1-3; R4 = R5(O)xCOCHR5CO(O)y(CH2)m; m = 2-10; x, y = 0-1; R5 = C1-5 alkyl; R6 = H, C1-5 alkyl, R7(O)zCO; z = 0-1; R7 = hydrocarbyl, may contain Si(OR2)nR33-n; R8 = C1-5 alkyl]. Corrosion-resistant metals coated with the compns. and optionally further coated with the organosilicon compds. are also claimed. Thus, adding dropwise a Na metasilicate soln. in THF, salting-out by NaCl, dehydrating the THF phase, and filtering gave a 18.6 g/L silicic acid/THF soln. A Zn-coated steel sheet (Zinkote) was degreased, coated with the THF soln. contg. 60 g/L (3-methacryloyloxypropyl)trimethoxysilane, and heated to give a test piece showing no corrosion in a salt spray test and good adhesion to a melamine-alkyd resin top coat.

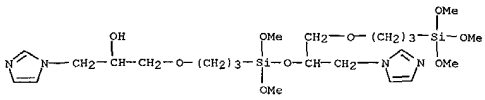
IT **205812-05-1P**
RL: IMF (Industrial manufacture); TEM (Technical or engineered material use); PREP (Preparation); USES (Uses)
(silicic acid copolymer-based anticorrosive coatings for metals with good adhesion to top coatings)

RN 205812-05-1 CAPLUS
CN Silicic acid (H2SiO3), polymer with 1-[(2,2-dimethoxy-1,6-dioxa-2-silacyclooct-8-yl)methyl]-1H-imidazole, .alpha.-[8-(1H-imidazol-1-ylmethyl)-6,6,14,14-tetramethoxy-2,7,10,15-tetraoxa-6,14-disilahexadec-1-yl]-1H-imidazole-1-ethanol and .alpha.-[[3-(trimethoxysilyl)propoxy]methyl]-1H-imidazole-1-ethanol (9CI) (CA INDEX NAME)

CM 1

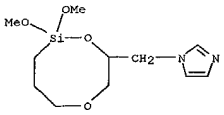
CRN 149394-84-3
CMF C23 H44 N4 O9 Si2

L3 ANSWER 23 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN (Continued)



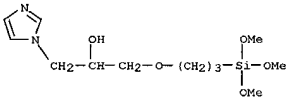
CM 2

CRN 149394-77-4
CMF C11 H20 N2 O4 Si



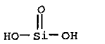
CM 3

CRN 149394-70-7
CMF C12 H24 N2 O5 Si



CM 4

CRN 7699-41-4
CMF H2 O3 Si

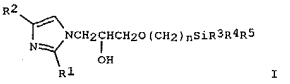


L3 ANSWER 23 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN (Continued)

L3 ANSWER 24 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN
ACCESSION NUMBER: 1997:496237 CAPLUS
DOCUMENT NUMBER: 127:116220
TITLE: Electrically conductive paste using imidazolesilane-coated copper powders
INVENTOR(S): Sasaki, Akihiro; Hirai, Keizo; Wada, Hiroshi
PATENT ASSIGNEE(S): Hitachi Chemical Co., Ltd., Japan
SOURCE: Jpn. Kokai Tokkyo Koho, 5 pp.
CODEN: JKXXAF
DOCUMENT TYPE: Patent
LANGUAGE: Japanese
FAMILY ACC. NUM. COUNT: 1
PATENT INFORMATION:

PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
JP 09180542	A2	19970711	JP 1995-337227	19951225

PRIORITY APPLN. INFO.: JP 1995-337227 19951225
OTHER SOURCE(S): MARPAT 127:116220
GI

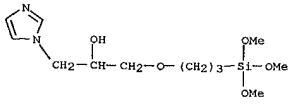


I

AB The conductive paste consists of (Ag-plated) Cu powders having av. diam. .ltoreq.30 .mu.m, coated with the imidazolesilane compd. I (antioxidant: R1-2 = H, alkyl, Ph, CN; R3-5 = H, alkyl, alkoxy; n = 1-5) in 0.0001-5 wt% to the Cu powders and dispersed in an org. solvent contg. a thermosetting resin (adhesive: e.g., phenolic resin, epoxy resin). The Cu powders preferably have a flake or dendritic shape for improved cond. The conductive paste, using the unexpensive materials, has good cond. even under high moisture.

IT **149394-70-7**, IS 1000
RL: TEM (Technical or engineered material use); USES (Uses)
(coating; elec. conductive paste using copper powders coated with imidazolesilane for oxidn. resistance)

RN 149394-70-7 CAPLUS
CN 1H-Imidazole-1-ethanol, .alpha.-[[3-(trimethoxysilyl)propoxy]methyl]- (9CI) (CA INDEX NAME)



L3 ANSWER 25 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN
ACCESSION NUMBER: 1997:475603 CAPLUS
DOCUMENT NUMBER: 127:149806
TITLE: Surface-treated fillers and polymer compositions using them
INVENTOR(S): Akutsu, Yoshinori; Kumagai, Masashi
PATENT ASSIGNEE(S): Japan Energy K. K., Japan
SOURCE: Jpn. Kokai Tokkyo Koho, 7 pp.
CODEN: JKXXAF
DOCUMENT TYPE: Patent
LANGUAGE: Japanese
FAMILY ACC. NUM. COUNT: 1
PATENT INFORMATION:

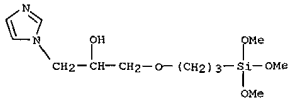
PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
JP 09169871	A2	19970630	JP 1995-332035	19951220

PRIORITY APPLN. INFO.: JP 1995-332035 19951220
GI

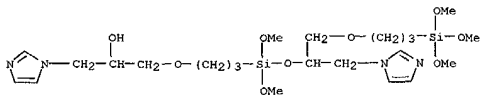
* STRUCTURE DIAGRAM TOO LARGE FOR DISPLAY - AVAILABLE VIA OFFLINE PRINT *

AB Title fillers are surface-treated with imidazole silanes of I, II, III, or their mixts. (R1 = H, vinyl, C1-5 alkyl; R2 = H, C1-20 alkyl; R3, R4 = C1-3 alkyl; n = 1-3). Polymer compns. comprising above fillers show good mech. strength and durability and are useful for elec. and electronic parts, adhesives, coatings, composites, etc. Thus, 100 parts ST 7 (silica) was mixed with a soln. (pH = 5) contg. 2 parts I-II-III (45:22:33) mixt. (R1 = R2 = H; R3 = Me; n = 3), 100 parts H2O-EtOH (1:1) mixt., and HCl, stirred one whole day and night, filtered, washed, and dried to give a surface-treated filler, 100 parts of which was mixed with Epikote 828 100, AH 154 (dicyandiamide) 5, and 2E4MZ (2-ethyl-4-methylimidazole) 1 part, poured into a mold, and cured to give a molding with good initial bending strength 107 N/mm2 (JIS K 6911).
IT **149394-70-7 149394-84-3**
RL: MOA (Modifier or additive use); PEP (Physical, engineering or chemical process); PROC (Process); USES (Uses)
(imidazole silane surface-treated fillers for polymer compns. with good mech. strength and durability)
RN 149394-70-7 CAPLUS
CN 1H-Imidazole-1-ethanol, .alpha.-[[3-(trimethoxysilyl)propoxy]methyl]- (9CI) (CA INDEX NAME)

L3 ANSWER 25 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN (Continued)



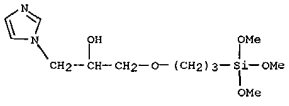
RN 149394-84-3 CAPLUS
CN 1H-Imidazole-1-ethanol, .alpha.-[8-(1H-imidazol-1-ylmethyl)-6,6,14,14-tetramethoxy-2,7,10,15-tetraoxa-6,14-disilahexadec-1-yl]- (9CI) (CA INDEX NAME)



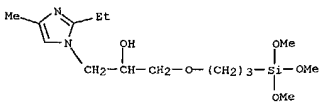
L3 ANSWER 26 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN
ACCESSION NUMBER: 1997:416261 CAPLUS
DOCUMENT NUMBER: 127:58050
TITLE: Solder resist composition containing silane compound with imidazole group
INVENTOR(S): Kodama, Yukio; Shoami, Shigeo; Kubota, Hiroyuki
PATENT ASSIGNEE(S): Toyo Ink Mfg. Co., Ltd., Japan
SOURCE: Jpn. Kokai Tokkyo Koho, 10 pp.
CODEN: JKXXAF
DOCUMENT TYPE: Patent
LANGUAGE: Japanese
FAMILY ACC. NUM. COUNT: 1
PATENT INFORMATION:

PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
JP 09114096	A2	19970502	JP 1995-266575	19951016

PRIORITY APPLN. INFO.: JP 1995-266575 19951016
AB The compn. contains an active ray-curable resin and a silane compd. with an imidazole group. The compn. shows good adhesion with Cu, good resistance to plating, chems., alkalis, solvents, and water.
IT **149394-70-7**, IS 1000 **149394-73-0 149394-76-3**
RL: MOA (Modifier or additive use); TEM (Technical or engineered material use); USES (Uses)
(solder resist compn. contg. curable resin and silane compd. with imidazole group)
RN 149394-70-7 CAPLUS
CN 1H-Imidazole-1-ethanol, .alpha.-[[3-(trimethoxysilyl)propoxy]methyl]- (9CI) (CA INDEX NAME)

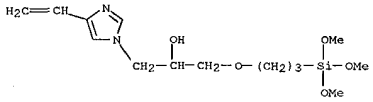


RN 149394-73-0 CAPLUS
CN 1H-Imidazole-1-ethanol, 2-ethyl-4-methyl-.alpha.-[[3-(trimethoxysilyl)propoxy]methyl]- (9CI) (CA INDEX NAME)



RN 149394-76-3 CAPLUS
CN 1H-Imidazole-1-ethanol, 4-ethenyl-.alpha.-[[3-(trimethoxysilyl)propoxy]methyl]- (9CI) (CA INDEX NAME)

L3 ANSWER 26 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN (Continued)



L3 ANSWER 27 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN
ACCESSION NUMBER: 1997:281228 CAPLUS
DOCUMENT NUMBER: 126:270385
TITLE: Photosolder resist composition containing inorganic filler treated with silane coupling agents
INVENTOR(S): Kubota, Hiroyuki
PATENT ASSIGNEE(S): Toyo Ink Mfg Co, Japan
SOURCE: Jpn. Kokai Tokkyo Koho, 11 pp.
CODEN: JKXXAF
DOCUMENT TYPE: Patent
LANGUAGE: Japanese
FAMILY ACC. NUM. COUNT: 1
PATENT INFORMATION:

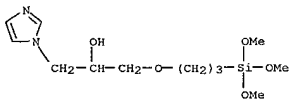
PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
JP 09043846	A2	19970214	JP 1995-266576	19951016

PRIORITY APPLN. INFO.: JP 1995-126177 19950525

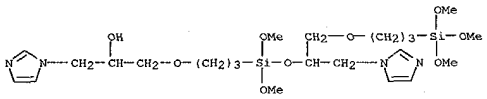
AB The compn. contains (A) an active energy ray-curable resin having carboxy group and alc. hydroxy group and (B) an inorg. filler pretreated with a silane coupling agent. The resist compn. shows good adhesion to Cu and durability.

IT **149394-70-7**, IS 1000
RL: MOA (Modifier or additive use); USES (Uses)
(IS 1000; photosolder resist compn. contg. inorg. filler treated with silane coupling agents to improve adhesion and durability)

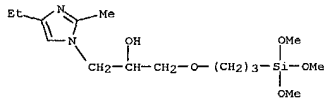
RN 149394-70-7 CAPLUS
CN 1H-Imidazole-1-ethanol, .alpha.-[[3-(trimethoxysilyl)propoxy]methyl]- (9CI) (CA INDEX NAME)



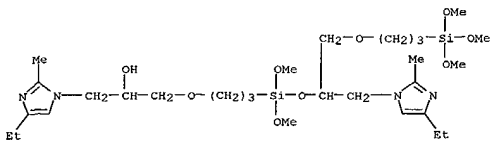
L3 ANSWER 28 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN (Continued)
NAME)



RN 187463-05-4 CAPLUS
CN 1H-Imidazole-1-ethanol, 4-ethyl-2-methyl-.alpha.-[[3-(trimethoxysilyl)propoxy]methyl]- (9CI) (CA INDEX NAME)



RN 187463-07-6 CAPLUS
CN 1H-Imidazole-1-ethanol, 4-ethyl-.alpha.-[8-[(4-ethyl-2-methyl-1H-imidazol-1-yl)methyl]-6,6,14,14-tetramethoxy-2,7,10,15-tetraoxa-6,14-disilahexadec-1-yl]-2-methyl- (9CI) (CA INDEX NAME)



L3 ANSWER 28 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN
ACCESSION NUMBER: 1997:203691 CAPLUS
DOCUMENT NUMBER: 126:200218
TITLE: Epoxy resin adhesive compositions and imidazole silanes for the compositions
INVENTOR(S): Akutsu, Yoshinori; Tsuchida, Katsuyuki; Kumagai, Masashi
PATENT ASSIGNEE(S): Japan Enajii Kk, Japan
SOURCE: Jpn. Kokai Tokkyo Koho, 9 pp.
CODEN: JKXXAF
DOCUMENT TYPE: Patent
LANGUAGE: Japanese
FAMILY ACC. NUM. COUNT: 1
PATENT INFORMATION:

PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
JP 09012683	A2	19970114	JP 1995-168669	19950704
JP 3396562	B2	20030414		

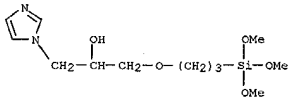
PRIORITY APPLN. INFO.: JP 1995-168669 19950704
GI

* STRUCTURE DIAGRAM TOO LARGE FOR DISPLAY - AVAILABLE VIA OFFLINE PRINT *

AB The compns., having good adhesion, comprise epoxy resin compns. contg. I, II, and/or III (R1 = H, vinyl, C1-5 alkyl; R2 = H, C1-20 alkyl; R3-4 = C1-3 alkyl; n = 1-3). Thus, an adhesive having shear strength (for bonging of stainless steel plates) 1.31 KN/cm2 was prepd. from Epikote 828
contg. 45:22:33 I, II and III mixt. (R1 = R2 = H; R3 = Me; n = 3) 1, AH 154 (dicyandiamide) 5 and 2-ethyl-4-methylimidazole 1 phr.

IT **149394-70-7 149394-84-3 187463-05-4 187463-07-6**
RL: MOA (Modifier or additive use); USES (Uses)
(epoxy resin adhesive compns. and imidazole silanes for the compns.)

RN 149394-70-7 CAPLUS
CN 1H-Imidazole-1-ethanol, .alpha.-[[3-(trimethoxysilyl)propoxy]methyl]- (9CI) (CA INDEX NAME)



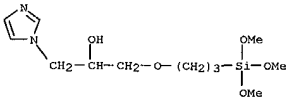
RN 149394-84-3 CAPLUS
CN 1H-Imidazole-1-ethanol, .alpha.-[8-(1H-imidazol-1-ylmethyl)-6,6,14,14-tetramethoxy-2,7,10,15-tetraoxa-6,14-disilahexadec-1-yl]- (9CI) (CA INDEX

L3 ANSWER 29 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN
ACCESSION NUMBER: 1996:512284 CAPLUS
DOCUMENT NUMBER: 125:223406
TITLE: The application of imidazolsilane to epoxy resin
AUTHOR(S): Akutsu, Yoshinori; Kumagai, Masashi
CORPORATE SOURCE: Maters. & Components Lab., Japan Energy Corp., Japan
SOURCE: Koen Yoshishu - Nippon Setchaku Gakkai Nenji Taikai (1996), 34th, 99-100
CODEN: KYNTFX
PUBLISHER: Nippon Setchaku Gakkai
DOCUMENT TYPE: Journal
LANGUAGE: Japanese

AB A new silane coupling agent was synthesized which has an imidazole group for promoting the epoxy resin curing.

IT **149394-70-7**
RL: CAT (Catalyst use); USES (Uses)
(application of imidazolsilane to epoxy resin)

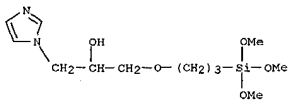
RN 149394-70-7 CAPLUS
CN 1H-Imidazole-1-ethanol, .alpha.-[[3-(trimethoxysilyl)propoxy]methyl]- (9CI) (CA INDEX NAME)



L3 ANSWER 30 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN
ACCESSION NUMBER: 1996:321194 CAPLUS
DOCUMENT NUMBER: 125:12409
TITLE: Copper-containing electroconductive materials and resin compositions
INVENTOR(S): Yoshida, Tomohito; Mukai, Yutaka
PATENT ASSIGNEE(S): Japan Enajii Kk, Japan
SOURCE: Jpn. Kokai Tokkyo Koho, 6 pp.
CODEN: JKXXAF
DOCUMENT TYPE: Patent
LANGUAGE: Japanese
FAMILY ACC. NUM. COUNT: 1
PATENT INFORMATION:

PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
JP 08048816	A2	19960220	JP 1994-319447	19941130
PRIORITY APPLN. INFO.:			JP 1994-43335	19940218
			JP 1994-144121	19940603

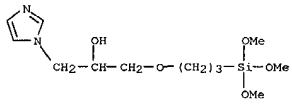
OTHER SOURCE(S): MARPAT 125:12409
AB The title compns., which have antistatic and electromagnetic wave-shielding properties, contain Cu-type electroconductive materials treated with imidazole silanes and titanate coupling agents. Thus, a pellet prepd. from 4700 JG (polypropylene) 79.7, CDA 6 [[2-HOC6H4CONHNHCO(CH2)5]2] 0.3, and carbon fibers 20 parts, which was plated with Cu, impregnated with ZCH2CH(OH)CH2O(CH2)3Si(OMe)3 (Z = imidazolyl), and sprayed with a titanate (KR-TTS), showed surface resistivity 6.6 .times. 10-2 .OMEGA./.box..
IT **149394-70-7**
RL: MOA (Modifier or additive use); USES (Uses)
(antistatic and electromagnetic-shielding resin compns. contg. copper treated with imidazole silane and titanate coupling agent)
RN 149394-70-7 CAPLUS
CN 1H-Imidazole-1-ethanol, .alpha.-[[3-(trimethoxysilyl)propoxy]methyl]- (9CI) (CA INDEX NAME)



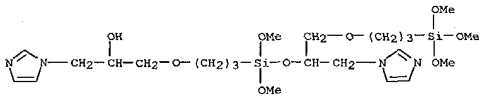
L3 ANSWER 31 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN
ACCESSION NUMBER: 1996:82920 CAPLUS
DOCUMENT NUMBER: 124:148341
TITLE: Surface treating agents for copper foils and their copper clad laminates
INVENTOR(S): Tsuchida, Katsuyuki; Kumagai, Masashi; Sasa, Naruaki; Akase, Fumiaki; Ogino, Yukio
PATENT ASSIGNEE(S): Japan Enajii K. K., Japan
SOURCE: Jpn. Kokai Tokkyo Koho, 6 pp.
CODEN: JKXXAF
DOCUMENT TYPE: Patent
LANGUAGE: Japanese
FAMILY ACC. NUM. COUNT: 1
PATENT INFORMATION:

PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
JP 07286160	A2	19951031	JP 1994-81541	19940420
PRIORITY APPLN. INFO.:			JP 1994-24142	19940222

AB The title treatment agents which improve adhesion of Cu foils and prepregs and solder heat resistance contain (A) trifunctional silanes YSiX3 (Y = org. functional group, hydrocarbon group contg. org. functional groups and optionally ether bond; X = hydrolyzable group) and (B) tetrafunctional silanes Si(OR)4 (R = hydrocarbon group which may contain ether bond). The title Cu clad laminate are composed of Cu foils with layers of the treatment agents and prepregs, which may be bonded via adhesive layers. Thus, electrolytic Cu foil was treated with copper pyrite on the rough side, plated with Zn or ZnO-Cr oxide, and coated with a AcOH soln. with pH 5 contg. 0.2% 3-glycidoxypropyltrimethoxysilane and 0.2% tetraethoxysilane and dried at 100.degree. to give a foil, which was press-heated with a a glass-epoxy resin prepreg, etched on the Cu foil side, and immersed in boiling water to show improved adhesion.
IT **149394-70-7 149394-84-3**
RL: MOA (Modifier or additive use); USES (Uses)
(silane surface treating agents for Cu foils and Cu clad laminates with boiling water resistance and adhesion)
RN 149394-70-7 CAPLUS
CN 1H-Imidazole-1-ethanol, .alpha.-[[3-(trimethoxysilyl)propoxy]methyl]- (9CI) (CA INDEX NAME)



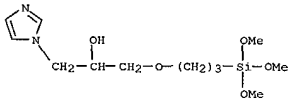
L3 ANSWER 31 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN (Continued)
RN 149394-84-3 CAPLUS
CN 1H-Imidazole-1-ethanol, .alpha.-[8-(1H-imidazol-1-ylmethyl)-6,6,14,14-tetramethoxy-2,7,10,15-tetraoxa-6,14-disilahexadec-1-yl]- (9CI) (CA INDEX NAME)



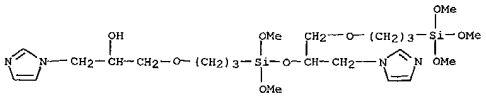
L3 ANSWER 32 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN
ACCESSION NUMBER: 1995:480174 CAPLUS
DOCUMENT NUMBER: 122:216756
TITLE: Silicon compound-based metal surface treating agents
INVENTOR(S): Tsuchida, Katsuyuki; Kumagai, Masashi; Ogino, Yukio
PATENT ASSIGNEE(S): Japan Enajii KK, Japan
SOURCE: Jpn. Kokai Tokkyo Koho, 8 pp.
CODEN: JKXXAF
DOCUMENT TYPE: Patent
LANGUAGE: Japanese
FAMILY ACC. NUM. COUNT: 1
PATENT INFORMATION:

PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
JP 06177535	A2	19940624	JP 1992-329304	19921209
PRIORITY APPLN. INFO.:			JP 1992-329304	19921209

OTHER SOURCE(S): MARPAT 122:216756
AB The title agents, giving good corrosion preventing and modified adhesion properties to metal surface, e.g., of Cu foils for printed circuit boards, comprise imidazole-contg. silane derivs. (e.g., reaction products of imidazole derivs. and 3-glycidoxypropyltrimethoxysilane) and bis(trialkoxy)silyl compds. [e.g., 1,2-bis(trimethoxy)silylethane].
IT **149394-70-7 149394-84-3**
RL: PEP (Physical, engineering or chemical process); PRP (Properties); PROC (Process)
(silicon compd.-based metal surface treating agents)
RN 149394-70-7 CAPLUS
CN 1H-Imidazole-1-ethanol, .alpha.-[[3-(trimethoxysilyl)propoxy]methyl]- (9CI) (CA INDEX NAME)



RN 149394-84-3 CAPLUS
CN 1H-Imidazole-1-ethanol, .alpha.-[8-(1H-imidazol-1-ylmethyl)-6,6,14,14-tetramethoxy-2,7,10,15-tetraoxa-6,14-disilahexadec-1-yl]- (9CI) (CA INDEX NAME)



L3 ANSWER 33 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN
ACCESSION NUMBER: 1993:507499 CAPLUS
DOCUMENT NUMBER: 119:107499
TITLE: Imidazole-silane compounds, their production and metal
surface finishing agent containing them
INVENTOR(S): Tsuchida, Katsuyuki; Kumagai, Masahi; Ogino, Yukio
PATENT ASSIGNEE(S): Nippon Mining Co. Ltd., Japan
SOURCE: Eur. Pat. Appl., 22 pp.
CODEN: EPXXDW
DOCUMENT TYPE: Patent
LANGUAGE: English
FAMILY ACC. NUM. COUNT: 1
PATENT INFORMATION:

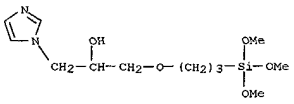
PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
EP 526847	A1	19930210	EP 1992-113067	19920731
R: DE, FR, GB				
JP 05186479	A2	19930727	JP 1992-183783	19920710
JP 07068256	B4	19950726		
US 5258522	A	19931102	US 1992-918454	19920722
PRIORITY APPLN. INFO.:			JP 1991-214181	19910801
			JP 1992-183783	19920710

AB Described is a novel imidazole-silane compd. which has an excellent heat resistance and a high corrosion preventive effect on a metal surface and is capable of remarkably improving the adhesion of a metal to a resin substrate, a process for prepg. such a compd., and a new metal surface finishing agent comprising the same. The novel imidazole-silane compd. is
produced by reacting an imidazole compd. with a 3-glycidoxypropylsilane compd. at 80 to 200.degree.. The surface finishing agents are used for copper foils for laminates for printed circuits.

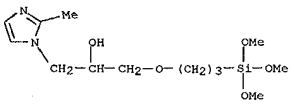
IT **149394-70-7P 149394-71-8P 149394-72-9P**
149394-73-0P 149394-74-1P 149394-75-2P
149394-76-3P 149394-84-3P 149394-85-4P
149394-86-5P 149394-87-6P 149394-88-7P
149394-89-8P 149394-90-1P 149394-91-2P
149394-92-3P 149394-93-4P 149394-97-8P
149394-98-9P 149394-99-0P 149395-00-6P
149395-01-7P 149395-02-8P 149395-03-9P
149395-08-4P 149395-09-5P 149395-10-8P
149395-11-9P 149395-12-0P 149395-13-1P
149395-14-2P 149395-18-6P 149395-19-7P
149395-20-0P
RL: PREP (Preparation)
(prepn. of, as metal surface finishing agents)

RN 149394-70-7 CAPLUS
CN 1H-Imidazole-1-ethanol, .alpha.-[[3-(trimethoxysilyl)propoxy]methyl]- (9CI) (CA INDEX NAME)

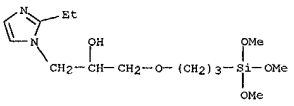
L3 ANSWER 33 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN (Continued)



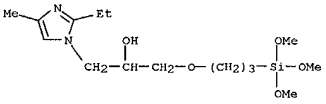
RN 149394-71-8 CAPLUS
CN 1H-Imidazole-1-ethanol, 2-methyl-.alpha.-[[3-(trimethoxysilyl)propoxy]methyl]- (9CI) (CA INDEX NAME)



RN 149394-72-9 CAPLUS
CN 1H-Imidazole-1-ethanol, 2-ethyl-.alpha.-[[3-(trimethoxysilyl)propoxy]methyl]- (9CI) (CA INDEX NAME)

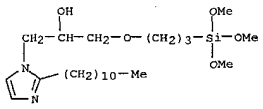


RN 149394-73-0 CAPLUS
CN 1H-Imidazole-1-ethanol, 2-ethyl-4-methyl-.alpha.-[[3-(trimethoxysilyl)propoxy]methyl]- (9CI) (CA INDEX NAME)

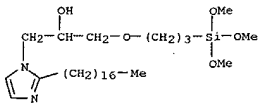


RN 149394-74-1 CAPLUS

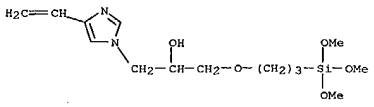
L3 ANSWER 33 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN (Continued)
CN 1H-Imidazole-1-ethanol, .alpha.-[[3-(trimethoxysilyl)propoxy]methyl]-2-undecyl- (9CI) (CA INDEX NAME)



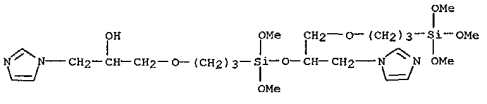
RN 149394-75-2 CAPLUS
CN 1H-Imidazole-1-ethanol, 2-heptadecyl-.alpha.-[[3-(trimethoxysilyl)propoxy]methyl]- (9CI) (CA INDEX NAME)



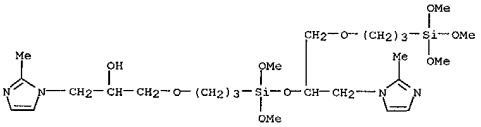
RN 149394-76-3 CAPLUS
CN 1H-Imidazole-1-ethanol, 4-ethenyl-.alpha.-[[3-(trimethoxysilyl)propoxy]methyl]- (9CI) (CA INDEX NAME)



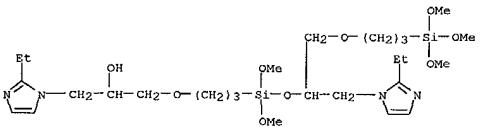
RN 149394-84-3 CAPLUS
CN 1H-Imidazole-1-ethanol, .alpha.-[8-(1H-imidazol-1-ylmethyl)-6,6,14,14-tetramethoxy-2,7,10,15-tetraoxa-6,14-disilahexadec-1-yl]- (9CI) (CA INDEX NAME)



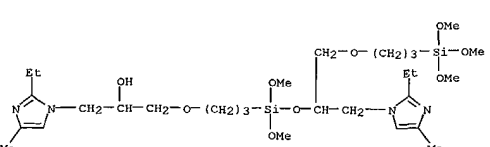
L3 ANSWER 33 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN (Continued)
RN 149394-85-4 CAPLUS
CN 1H-Imidazole-1-ethanol, 2-methyl-.alpha.-[6,6,14,14-tetramethoxy-8-[(2-methyl-1H-imidazol-1-yl)methyl]-2,7,10,15-tetraoxa-6,14-disilahexadec-1-yl]- (9CI) (CA INDEX NAME)



RN 149394-86-5 CAPLUS
CN 1H-Imidazole-1-ethanol, 2-ethyl-.alpha.-[8-[(2-ethyl-1H-imidazol-1-yl)methyl]-6,6,14,14-tetramethoxy-2,7,10,15-tetraoxa-6,14-disilahexadec-1-yl]- (9CI) (CA INDEX NAME)



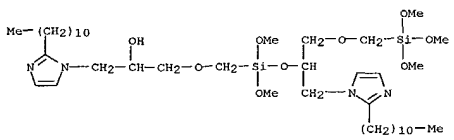
RN 149394-87-6 CAPLUS
CN 1H-Imidazole-1-ethanol, 2-ethyl-.alpha.-[8-[(2-ethyl-4-methyl-1H-imidazol-1-yl)methyl]-6,6,14,14-tetramethoxy-2,7,10,15-tetraoxa-6,14-disilahexadec-1-yl]-4-methyl- (9CI) (CA INDEX NAME)



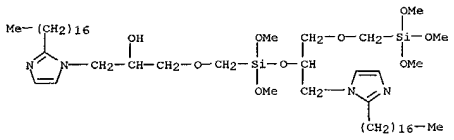
RN 149394-88-7 CAPLUS
CN 1H-Imidazole-1-ethanol, .alpha.-[4,4,10,10-tetramethoxy-6-[(2-undecyl-1H-imidazol-1-yl)methyl]-2,5,8,11-tetraoxa-4,10-disiladodec-1-yl]-2-undecyl- (9CI) (CA INDEX NAME)

Kamal Saeed

L3 ANSWER 33 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN (Continued)

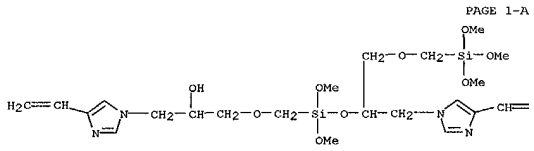


RN 149394-89-8 CAPLUS
CN 1H-Imidazole-1-ethanol, 2-heptadecyl-.alpha.-[6-[(2-heptadecyl-1H-imidazol-1-yl)methyl]-4,4,10,10-tetramethoxy-2,5,8,11-tetraoxa-4,10-disiladodec-1-yl]- (9CI) (CA INDEX NAME)



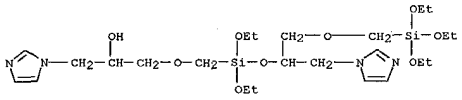
RN 149394-90-1 CAPLUS
CN 1H-Imidazole-1-ethanol, 4-ethenyl-.alpha.-[6-[(4-ethenyl-1H-imidazol-1-yl)methyl]-4,4,10,10-tetramethoxy-2,5,8,11-tetraoxa-4,10-disiladodec-1-yl]- (9CI) (CA INDEX NAME)

PAGE 1-A

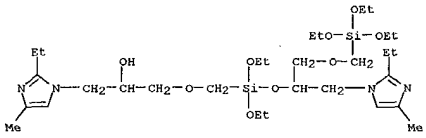


L3 ANSWER 33 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN (Continued)

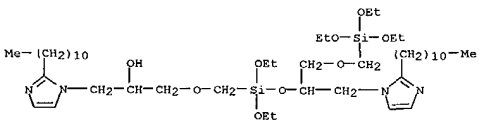
RN 149394-97-8 CAPLUS
CN 1H-Imidazole-1-ethanol, .alpha.-[4,4,10,10-tetraethoxy-6-(1H-imidazol-1-ylmethyl)-2,5,8,11-tetraoxa-4,10-disilatridec-1-yl]- (9CI) (CA INDEX NAME)



RN 149394-98-9 CAPLUS
CN 1H-Imidazole-1-ethanol, 2-ethyl-4-methyl-.alpha.-[4,4,10,10-tetraethoxy-6-[(2-ethyl-4-methyl-1H-imidazol-1-yl)methyl]-2,5,8,11-tetraoxa-4,10-disilatridec-1-yl]- (9CI) (CA INDEX NAME)



RN 149394-99-0 CAPLUS
CN 1H-Imidazole-1-ethanol, .alpha.-[4,4,10,10-tetraethoxy-6-[(2-undecyl-1H-imidazol-1-yl)methyl]-2,5,8,11-tetraoxa-4,10-disilatridec-1-yl]-2-undecyl- (9CI) (CA INDEX NAME)

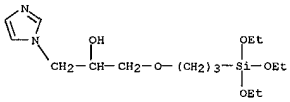


RN 149395-00-6 CAPLUS
CN 1H-Imidazole-1-ethanol, .alpha.-[[3-(dimethoxymethylsilyl)propoxy]methyl]- (9CI) (CA INDEX NAME)

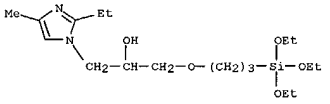
L3 ANSWER 33 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN (Continued)

PAGE 1-B

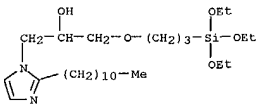
RN 149394-91-2 CAPLUS
CN 1H-Imidazole-1-ethanol, .alpha.-[[3-(triethoxysilyl)propoxy]methyl]- (9CI) (CA INDEX NAME)



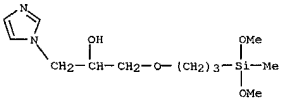
RN 149394-92-3 CAPLUS
CN 1H-Imidazole-1-ethanol, 2-ethyl-4-methyl-.alpha.-[[3-(triethoxysilyl)propoxy]methyl]- (9CI) (CA INDEX NAME)



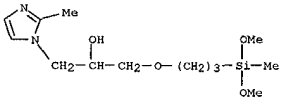
RN 149394-93-4 CAPLUS
CN 1H-Imidazole-1-ethanol, .alpha.-[[3-(triethoxysilyl)propoxy]methyl]-2-undecyl- (9CI) (CA INDEX NAME)



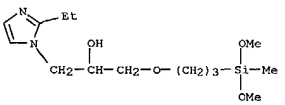
L3 ANSWER 33 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN (Continued)



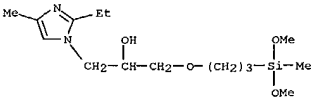
RN 149395-01-7 CAPLUS
CN 1H-Imidazole-1-ethanol, .alpha.-[[3-(dimethoxymethylsilyl)propoxy]methyl]-2-methyl- (9CI) (CA INDEX NAME)



RN 149395-02-8 CAPLUS
CN 1H-Imidazole-1-ethanol, .alpha.-[[3-(dimethoxymethylsilyl)propoxy]methyl]-2-ethyl- (9CI) (CA INDEX NAME)

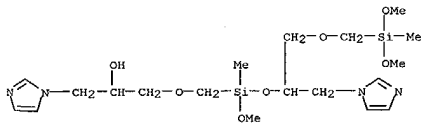


RN 149395-03-9 CAPLUS
CN 1H-Imidazole-1-ethanol, .alpha.-[[3-(dimethoxymethylsilyl)propoxy]methyl]-2-ethyl-4-methyl- (9CI) (CA INDEX NAME)

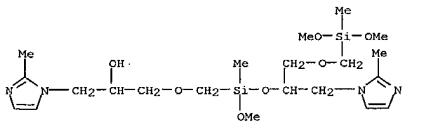


RN 149395-08-4 CAPLUS
CN 1H-Imidazole-1-ethanol, .alpha.-[6-(1H-imidazol-1-ylmethyl)-4,10-dimethoxy-4,10-dimethyl-2,5,8,11-tetraoxa-4,10-disiladodec-1-yl]- (9CI) (CA INDEX

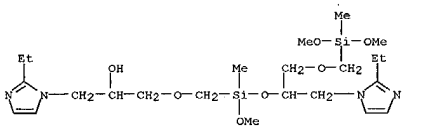
L3 ANSWER 33 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN (Continued)
NAME)



RN 149395-09-5 CAPLUS
CN 1H-Imidazole-1-ethanol,
.alpha.-[4,10-dimethoxy-4,10-dimethyl-6-[(2-methyl-
1H-imidazol-1-yl)methyl]-2,5,8,11-tetraoxa-4,10-disiladodec-1-yl]-2-methyl-
(9CI) (CA INDEX NAME)

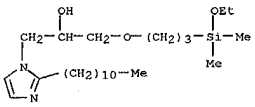


RN 149395-10-8 CAPLUS
CN 1H-Imidazole-1-ethanol, 2-ethyl-.alpha.-[6-[(2-ethyl-1H-imidazol-1-
yl)methyl]-4,10-dimethoxy-4,10-dimethyl-2,5,8,11-tetraoxa-4,10-disiladodec-
1-yl]- (9CI) (CA INDEX NAME)

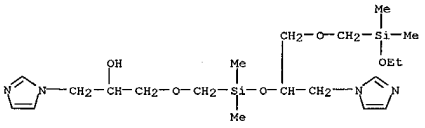


RN 149395-11-9 CAPLUS
CN 1H-Imidazole-1-ethanol,
2-ethyl-.alpha.-[6-[(2-ethyl-4-methyl-1H-imidazol-
1-yl)methyl]-4,10-dimethoxy-4,10-dimethyl-2,5,8,11-tetraoxa-4,10-

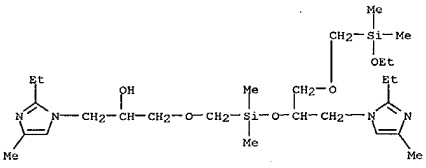
L3 ANSWER 33 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN (Continued)



RN 149395-18-6 CAPLUS
CN 1H-Imidazole-1-ethanol, .alpha.-[6-(1H-imidazol-1-ylmethyl)-4,4,10,10-
tetramethyl-2,5,8,11-tetraoxa-4,10-disilatridec-1-yl]- (9CI) (CA INDEX
NAME)

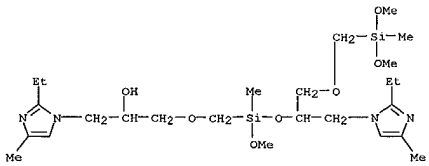


RN 149395-19-7 CAPLUS
CN 1H-Imidazole-1-ethanol,
2-ethyl-.alpha.-[6-[(2-ethyl-4-methyl-1H-imidazol-
1-yl)methyl]-4,4,10,10-tetramethyl-2,5,8,11-tetraoxa-4,10-disilatridec-1-
yl]-4-methyl- (9CI) (CA INDEX NAME)

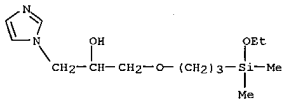


RN 149395-20-0 CAPLUS
CN 1H-Imidazole-1-ethanol, .alpha.-[4,4,10,10-tetramethyl-6-[(2-undecyl-1H-
imidazol-1-yl)methyl]-2,5,8,11-tetraoxa-4,10-disilatridec-1-yl]-2-undecyl-
(9CI) (CA INDEX NAME)

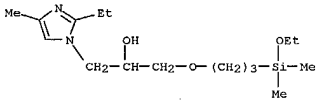
L3 ANSWER 33 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN (Continued)
disiladodec-1-yl)-4-methyl- (9CI) (CA INDEX NAME)



RN 149395-12-0 CAPLUS
CN 1H-Imidazole-1-ethanol, .alpha.-[[3-(ethoxydimethylsilyl)propoxy]methyl]-
(9CI) (CA INDEX NAME)

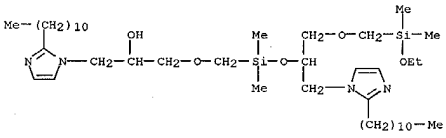


RN 149395-13-1 CAPLUS
CN 1H-Imidazole-1-ethanol,
.alpha.-[[3-(ethoxydimethylsilyl)propoxy]methyl]-2-
ethyl-4-methyl- (9CI) (CA INDEX NAME)



RN 149395-14-2 CAPLUS
CN 1H-Imidazole-1-ethanol,
.alpha.-[[3-(ethoxydimethylsilyl)propoxy]methyl]-2-
undecyl- (9CI) (CA INDEX NAME)

L3 ANSWER 33 OF 33 CAPLUS COPYRIGHT 2003 ACS on STN (Continued)



09936073 24/09/2003

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FULL ESTIMATED COST	153.44	301.80

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CA SUBSCRIBER PRICE	-21.48	-21.48

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FULL ESTIMATED COST	0.12	301.92

DISCOUNT AMOUNTS (FOR QUALIFYING ACCOUNTS)	SINCE FILE ENTRY	TOTAL SESSION
CA SUBSCRIBER PRICE	0.00	-21.48

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Kamal Saeed